

# **Design Document**

## **EN2160 - Electronic Design Realization**



Department of Electronic and Telecommunication Engineering  
University of Moratuwa

## **Capacitive Torque Sensor**

### **Group Members:**

De Zoysa.A.S.I - 220106D  
Dayananthan.T - 220096T  
Mathujan.S - 220389U  
Pirathishanth.A - 220480P  
Jeyasekara.S.P.R - 220257N  
Sulojan.R - 220626V  
Ananthakumar.T - 220029T  
Ahilakumaran.T - 220017F

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# 1 General Introduction

## 1.1 Overview

Torque measurement is a critical aspect in various mechanical and electromechanical systems, playing a vital role in applications ranging from industrial automation and automotive systems to robotics and biomedical devices. Accurate and reliable torque sensing is essential for performance monitoring, control, and safety in rotating machinery.

Conventional torque sensors such as strain gauge-based sensors and magnetoelastic sensors, while widely used, often suffer from limitations including sensitivity to environmental disturbances, mechanical wear, and complex signal conditioning requirements. In contrast, capacitive sensing offers a promising alternative due to its high sensitivity, low power consumption, compact form factor, and compatibility with modern digital signal processing techniques.

## 1.2 Functionality

This project focuses on the design and development of a **Capacitive Torque Sensor**, which operates based on the principle that the application of torque to a shaft induces a mechanical twist, resulting in a change in capacitance between specially arranged conductive plates. By accurately detecting and processing these capacitance variations, the system can quantify the applied torque.

The primary objective of this project is to develop a compact, sensitive, and cost-effective capacitive torque sensor that can be integrated into rotating machinery. The proposed system includes a high-resolution capacitance-to-digital converter (PCAP04), innovative plate designs to enhance sensitivity, and a digital telemetry system to wirelessly transmit data from the rotating shaft to a stationary receiver.

This report outlines the background theory, concept development, system design, component selection, and the overall implementation strategy of the capacitive torque sensing solution. The project aims to bridge the gap between theoretical torque measurement principles and practical, deployable sensor systems suitable for real-world engineering applications.

## 2 User Need Analysis

After observing videos of torque sensors used by individuals, we can get a sense of what they expect from a product and how they interact with existing products. It is also possible to see where current solutions cause inconveniences and frustrations to users and give us an idea about how to improve what is already available.

- **Light Weight:** First thing that was observed was the fact that individuals in videos handled the sensors often with one hand. This shows that the designed sensor has to be lightweight enough for users to handle comfortably. Also there were footages of torque sensors being attached to robot joints. Making the sensors heavy would put additional strain on limbs of the robot.
- **Accuracy and Precision:** There were videos of torque sensors being used in robots which did pick and placing of objects as well as medical robots which performed surgeries. Accuracy and precision of the measurements are critical in these scenarios since that data is fed into the control system for the robot.
- **Structural Rigidity:** Since there are deforming parts inside the sensor, it must be made sure that no part will be permanently deformed. Otherwise, it will require frequent sensor replacement. Proper material analysis and finite element analysis is required for this.
- **Easy to set up:** The sensors we observed had one cable attaching it to computers. The data from the sensor and the power to sensor is supplied through that. If users were able to use the sensor with no(minimal) calibration and set-up procedure, it would improve their experience of using the product.
- **Stability over time and Environmental Condition:** The sensor readings can change over time due to internal components being worn out(Sensor Drift). Environmental factors such as humidity and temperature can also affect capacitance. Users will require sensors that compensate for these issues.

### 2.1 Stakeholder Mapping

To develop a successful capacitive torque sensor, it is essential to identify the primary stakeholders who will interact with the product.

**Figure 1: Stakeholder map for Capacitive Torque Sensor**

- **Industrial Robotics Engineers** – Require precise torque measurement for automation and robotics applications.
- **Automotive Manufacturers** – Need reliable sensors for vehicle powertrain testing and safety applications.
- **Aerospace Engineers** – Use torque sensors in flight control systems and component testing.
- **Medical Device Developers** – Apply torque sensors in robotic surgery and rehabilitation equipment.
- **Research Institutions** – Require torque sensors for mechanical testing and material studies.

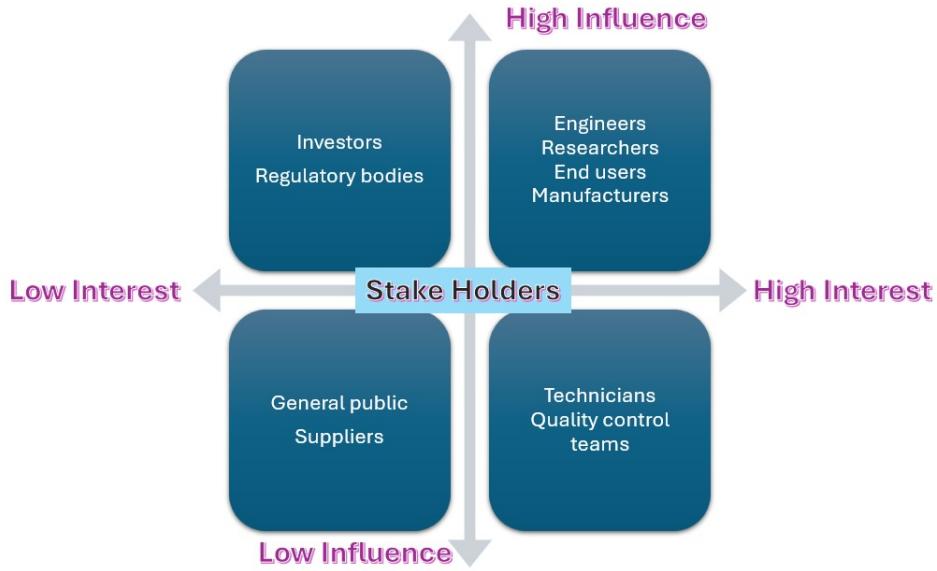


Figure 1: Stake holder Map

## 2.2 User Analysis: What a User Requires from a Capacitive Torque Sensor

A capacitive torque sensor is a critical component in automation, robotics, and industrial applications where precise force and torque measurements are required. Users of these sensors have specific requirements depending on the application domain. Based on two available industry sensors — **WACOH-TECH Dyn Pick** and the **Robotous RFT-Series** — the following key user requirements have been identified:

### High Accuracy and Sensitivity

- Users require sensors with high resolution and sensitivity to detect even minor force variations.
- The RFT-Series provides resolutions as low as 0.08 N (force) and 0.004 Nm (torque) for high-precision applications.

### Real-Time Data Acquisition and Communication Interfaces

- High-speed data acquisition is necessary to enable real-time control in robotics and automation.
- **EtherCAT Interface:** Ensures low-latency, high-speed communication.
- **Multi-Protocol Support:** CAN, RS-232, RS-422, and USB connectivity for compatibility.

### Durability and Environmental Resistance

- Must withstand overload without losing calibration.
- WACOH-TECH Dyn Pick features an internal stopper mechanism.
- RFT-Series includes temperature compensation and IP65 ingress protection.

## **Compact and Lightweight Design**

- Small size and weight are essential for robotic integration.
- RFT-Series models range from 60 g to 294 g while maintaining high performance.

## **Ease of Installation and Maintenance**

- Plug-and-play mounting, embedded EtherCAT boards, and built-in signal processing reduce setup time.
- Dyn Pick features integrated microcomputers that auto-correct signals.

## **Cost-Effectiveness and Customization**

- Offers a cost-efficient alternative to strain-gauge sensors.
- Custom calibration and mechanical designs for special use cases.

## **Safety and Overload Protection**

- Overload detection and protection features are critical.
- RFT-Series includes overload counters; Dyn Pick includes mechanical stoppers.

## **Summary of User Requirements**

| Requirement        | Description   |
|--------------------|---|
| High Accuracy      | Precision as low as 0.08 N (force) and 0.004 Nm (torque) for detailed measurements.           |
| Real-Time Data     | EtherCAT, CAN, and RS-232 support for industrial automation and robotics.                     |
| Durability         | Overload protection, temperature compensation, and IP65 sealing for reliability.              |
| Compact Design     | Lightweight models (60 g–294 g) for easy integration into robotic arms and automation setups. |
| Easy Installation  | Plug-and-play EtherCAT and built-in microcomputers for signal correction.                     |
| Cost-Effectiveness | Low-cost capacitive sensors compared to strain-gauge alternatives.                            |
| Safety             | Overload detection counters and mechanical stoppers prevent sensor damage.                    |

Table 1: Summary of Capacitive Torque Sensor User Requirements

## **2.3 Personas (User Categories)**

Based on stakeholder observations, the following user personas were identified:

### **Persona 1: Robotics Engineer**

**Needs:** High-precision real-time torque feedback, compact design, EtherCAT connectivity.

**Challenges:** Existing sensors are costly and lack high-frequency response.

### **Persona 2: Automotive Test Engineer**

**Needs:** Durable sensor for vehicle testing, CAN bus compatibility, high load-bearing capacity.

**Challenges:** Traditional sensors suffer from mechanical wear and require frequent calibration.

### **Persona 3: Research Scientist**

**Needs:** High-resolution measurements, low-noise data acquisition, digital interfacing options.

**Challenges:** Strain-gauge sensors provide unstable long-term readings, affecting research accuracy.

## **2.4 User Journey: From Manufacturing to End-of-Life**

### **2.4.1 1. Manufacturing and Assembly**

- Components such as capacitive plates, microcontrollers, and housings are sourced.
- Fabrication and calibration of sensing elements are performed.
- Final assembly and quality control are completed.

### **2.4.2 2. Distribution and Supply Chain**

- Sensors shipped to OEMs and distributors in robotics, automotive, and medical industries.
- Integrated into robotic arms, test benches, and machinery.

### **2.4.3 3. Deployment and Operation**

- Engineers and researchers implement sensors in real-world applications.
- Sensors provide real-time torque feedback.
- Interfaces like EtherCAT and CAN ensure compatibility.

### **2.4.4 4. Maintenance and Calibration**

- Regular calibration ensures accuracy.
- Firmware updates maintain compatibility.
- Inspections identify wear and damage.

### **2.4.5 5. End-of-Life: Repair, Recycling, or Disposal**

- Repair includes calibration, part replacement, or firmware updates.
- Recyclable materials (e.g., aluminum, PCBs) are salvaged.
- Disposal complies with environmental safety regulations.

## 2.5 Needs List & Key Design Considerations

Based on user observations, the following needs and considerations are identified:

- **High sensitivity** – Detect small torque variations with precision.
- **Non-contact measurement** – Capacitive sensing avoids mechanical wear.
- **Multi-protocol communication** – EtherCAT and CAN support for integration.
- **Compact and lightweight** – Important for robotics and aerospace.
- **High environmental resistance** – Resilient to temperature, dust, and moisture.
- **Real-time data acquisition** – Critical for dynamic applications.
- **Sustainable End-of-Life Strategy** – Emphasis on recyclability and repairability.

### 3 Stimulate Ideas

To explore innovative approaches for measuring torque using capacitive sensing, we engaged in brainstorming sessions and concept generation techniques. Our goal was to identify methods that not only leverage the capacitive principle but also overcome practical limitations in real-world applications.

#### 5.1 Basic Principle

The core idea behind capacitive torque sensing is based on the measurement of changes in capacitance caused by the deformation of a structure under torque. When a torque is applied to a shaft, it induces a slight twist or displacement. If capacitive plates are positioned in a way that their relative alignment changes with this twist, the resulting change in capacitance can be correlated directly to the applied torque.

#### 5.2 Initial Concept: Variable Overlap Capacitive Plates

Our starting concept used interdigitated electrodes—alternating conductive fingers mounted on both rotating and stationary parts of the shaft. As the shaft twists under torque, the overlap area between these electrodes changes, altering the capacitance. This variation can be measured and processed to derive the torque.

To increase sensitivity and resolution, we explored the use of **high-permittivity dielectric materials** placed between the electrode pairs. This enhancement significantly amplifies the measurable capacitance change, making the sensor more responsive to even small torque variations.

#### 5.3 Advanced Concept: Parallel-Plate Design with Radial Displacement

We developed an alternative design where capacitive plates are arranged radially around the shaft. Under torque, one plate set rotates slightly with the shaft, causing radial displacement relative to the stationary plates. This geometry maximizes the effect of twist on capacitance and allows for compact sensor integration.

#### 5.4 Signal Acquisition and Processing

A major challenge with capacitive torque sensors is accurately capturing the small capacitance changes, especially in noisy environments. We selected the **PCAP04 capacitance-to-digital converter (CDC)** for its precision and low noise characteristics. This IC allows real-time digital readout of capacitance variations with high resolution.

To improve performance further, we considered **differential measurement techniques**, using a reference capacitor to eliminate common-mode noise and temperature effects.

## 4 Our Approach

In the initial phase of our project, we conducted extensive background research on capacitive torque sensing technologies. A key reference was the patent titled **Differential Capacitive Torque Sensor**, which disclosed a multi-disk configuration for torque measurement. Building on this concept, we developed a modified three-disk assembly optimized for sensitivity and manufacturability.

### 4.1 Mechanical Design

Our sensor consists of three coaxial disks (Figure 2):

- **Rotor 1A and Rotor 1B:** Two outer **metal disks**, fixed to the stationary housing (stator). These serve as the capacitive sensing electrodes.
- **Rotor 2:** A central **dielectric disk**, rigidly attached to the rotating shaft. Its angular displacement under torque modulates the overlapping area between the metal disks.

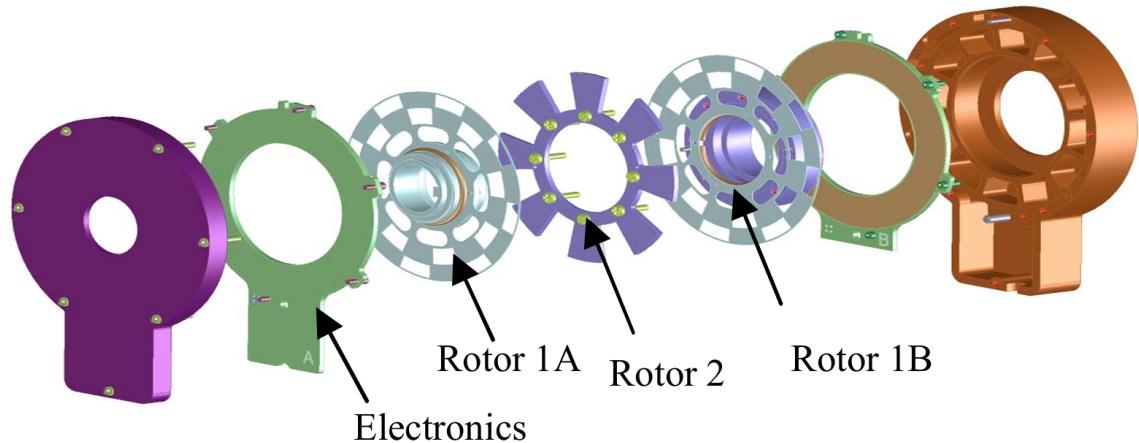


Figure 2: Exploded view of the sensor assembly. The central dielectric disk (Rotor 2) rotates with the shaft, while the outer metal disks (Rotor 1A/B, gray) remain stationary.

### 4.2 Working Principle

When torque is applied:

1. The shaft twists, causing the dielectric disk (Rotor 2) to rotate relative to the fixed metal disks.
2. This rotation changes the effective overlapping area between the dielectric and metal disks, creating a **differential capacitance** (Figure 3).
3. The capacitance variation is measured by electronics connected to the metal disks, proportional to the applied torque.

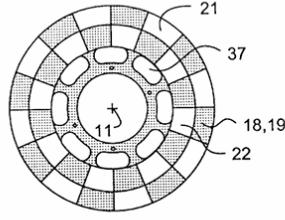


FIG. 5

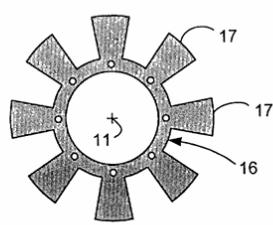


FIG. 6

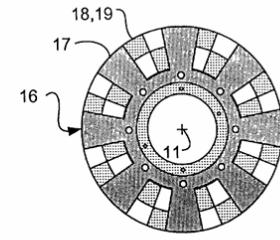


FIG. 7

Figure 3: Top-down views of disk geometries: (a) Metal disks (Rotor 1A/1B) with symmetric electrode patterns; (b) Dielectric disk (Rotor 2) with alternating permittivity regions.

#### 4.3 Advantages of the Three-Disk Configuration

- **Enhanced Sensitivity:** The dielectric disk amplifies capacitance changes compared to air gaps.
- **Reduced Crosstalk:** Fixed metal disks minimize parasitic capacitances from shaft movement.
- **Linear Response:** The symmetric design ensures a linear relationship between torque and capacitance.

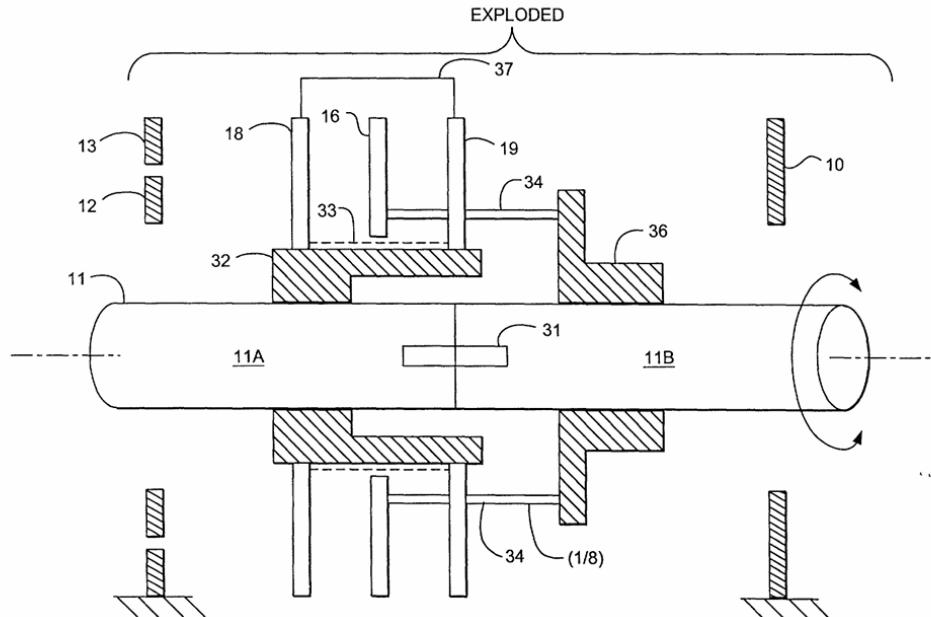


Figure 4: Cross-sectional schematic showing torque transfer (blue arrows) and capacitive coupling (red fields) between disks. The dielectric disk's rotation modulates the electric field between the metal disks.

This design, inspired by the patent but refined for our application, ensures reliable torque measurement while simplifying assembly and calibration.

## 5 Design and Development Timeline

The product development followed a systematic approach with the following chronological stages:

### 1. Research About Existing Products - (Week 05)

- Investigated similar products in the market
- Analyzed about patents or Research papers about product
- Identified gaps and improvement of existing product

### 2. Conceptual Design Modeling - (Week 06)

- Developed initial concept sketches
- Created basic 3D models of key components
- Evaluated different design approaches

### 3. SolidWorks Modeling Iteration 01 - (Week 07)

- First complete 3D CAD model of the assembly
- Focused on overall dimensions and form factor
- Identified major mechanical interfaces

### 4. FEA Analysis for Shaft - (Week 08)

- Performed stress analysis on critical shaft components
- Evaluated deformation under various Torque values
- Optimized material selection based on results

### 5. SolidWorks Modeling Iteration 02 - (Week 08)

- Incorporated FEA feedback into design
- Refined mechanical interfaces
- Improved ergonomics and manufacturability

### 6. Calculations for Components and Component Selection - (Week 09)

- Performed engineering calculations for Capacitance, CDC and MCU
- Selected appropriate bearings, products, and materials
- Verified component specifications against requirements

### 7. SolidWorks Modeling Iteration 03 - (Week 10)

- Finalized 3D model with all components and Sir's advice and Guidance
- Changed the overall enclosure design aligned with our reference product
- Prepared technical drawings for production

### 8. Schematics Design - (Week 11)

- Developed electronic circuit diagrams
- Selected appropriate sensors and ICs
- Designed power distribution network

**9. PCB Design - (Week 12)**

- Created 4-layer board layout in Altium Designer
- Optimized for signal integrity and EMI
- Incorporated capacitive sensing functionality

**10. Metal Cutting and Making Enclosures - (Week 13)**

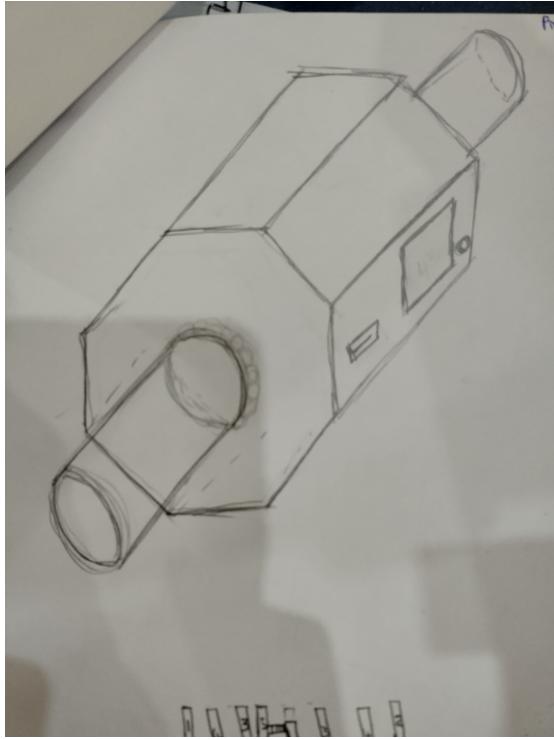
- Manufactured disks and mechanical components
- Fabricated custom enclosures
- Machined shaft to precise specifications

**11. Assembling Mechanical Parts - (Week 14)**

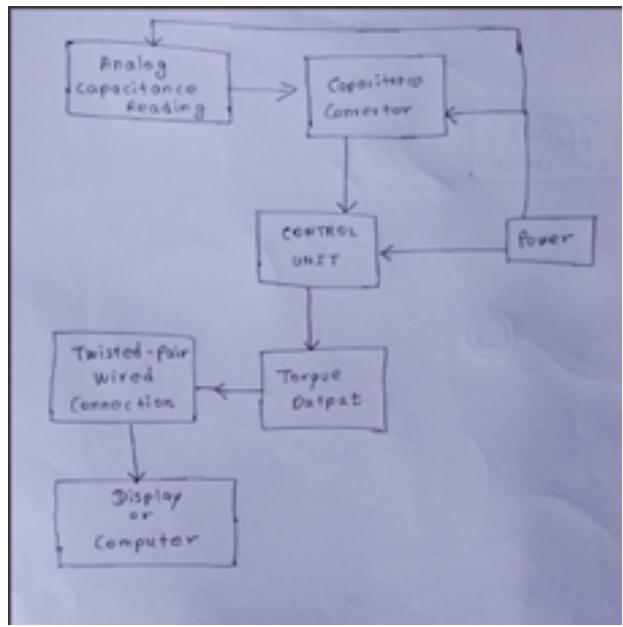
- Verified fit and function of all components
- Performed alignment and calibration
- Prepared final assembly for testing

## 6 Conceptual Designs

### 6.1 Conceptual Design 1



(a) Enclosure and Shaft Design



(b) Block Diagram

#### Enclosure Design

The hexagonal enclosure with cylindrical shafts is compact and stable for housing capacitive electrodes. A non-conductive material is recommended to avoid interference.

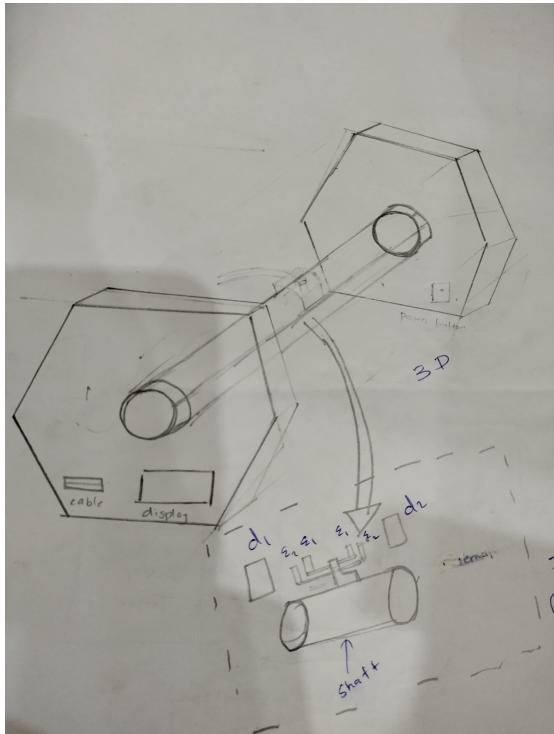
#### Shaft Design

The cylindrical shafts enable torque transmission and deformation for capacitance measurement. Adding a high-permittivity dielectric, as suggested in prior methodologies, could enhance sensitivity.

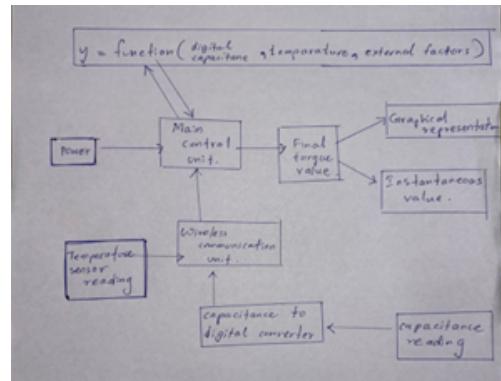
#### Block Diagram

The system converts analog capacitance readings into torque output via a control unit, using a twisted-pair wired connection for reliable data transfer. Wireless telemetry could improve flexibility.

## 6.2 Conceptual Design 2



(a) Enclosure and Shaft Design



(b) Block Diagram

Figure 6: Conceptual Design 2

### Enclosure Design

The dual hexagonal enclosures with cylindrical shafts provide structural stability for housing capacitive electrodes. The compact design suits space-limited applications, but a non-conductive material is essential to prevent interference.

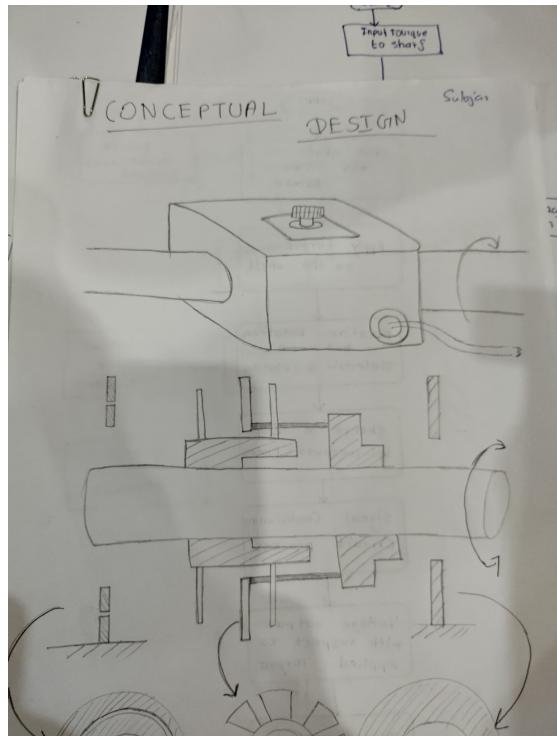
### Shaft Design

The cylindrical shaft connecting the enclosures transmits torque, enabling deformation for capacitance measurement. Dimensions (d<sub>1</sub>, d<sub>2</sub>, 3D) suggest a focus on precision, but a high-permittivity dielectric could enhance sensitivity.

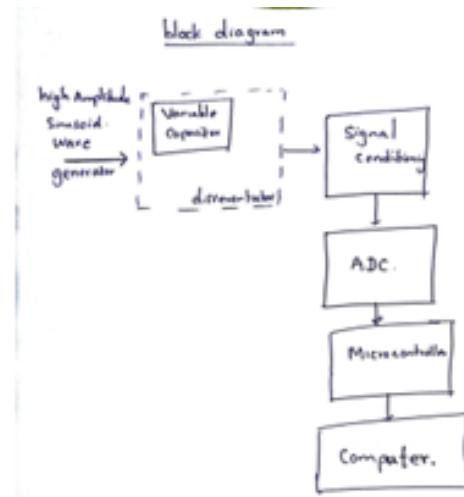
### Block Diagram

The system uses a capacitance-to-digital converter to process readings, feeding into a main control unit. Wireless communication transmits the final torque value to a graphical representation on a display or PC. Temperature sensor readings account for external factors, improving accuracy.

### 6.3 Conceptual Design 3



(a) Enclosure and Shaft Design



(b) Block Diagram

Figure 7: Conceptual Design 3

#### Enclosure Design

The rectangular enclosure with cylindrical shafts provides a stable housing for the capacitive sensor. Its design supports integration into a rotary system, but using a non-conductive material is critical to avoid interference.

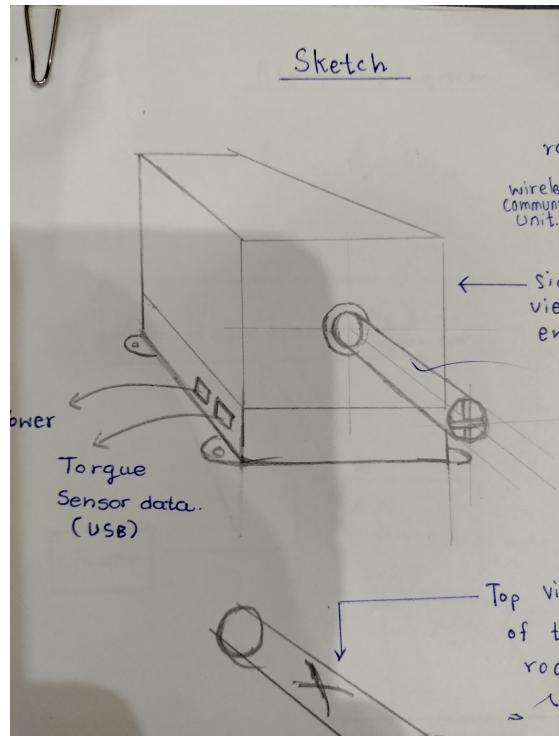
#### Shaft Design

The cylindrical shaft, with a gear-like component, transmits torque, causing deformation for capacitance measurement. The gear may aid in precise torque application, but a high-permittivity dielectric could improve sensitivity.

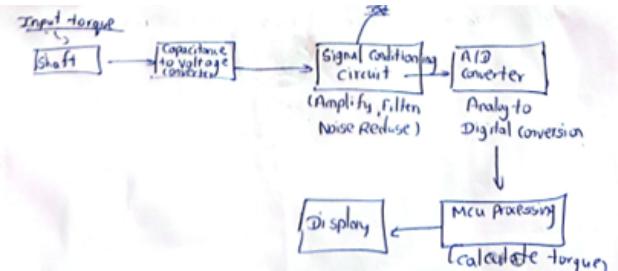
#### Block Diagram

A high-amplitude sinusoidal wave generator powers a variable capacitor (distometer), feeding into signal conditioning, an ADC, and a microcontroller, with final output to a computer. This setup converts capacitance changes into digital torque data effectively.

## 6.4 Conceptual Design 4



(a) Enclosure and Shaft Design



(b) Block Diagram

Figure 8: Conceptual Design 4

### Enclosure Design

The rectangular enclosure with a cylindrical shaft is sturdy for housing the sensor. Feet on the base suggest stable mounting, but a non-conductive material is necessary to avoid interference.

### Shaft Design

The cylindrical shaft transmits torque, enabling deformation for capacitance measurement. The top view shows a rod for torque input, but a high-permittivity dielectric could improve sensitivity.

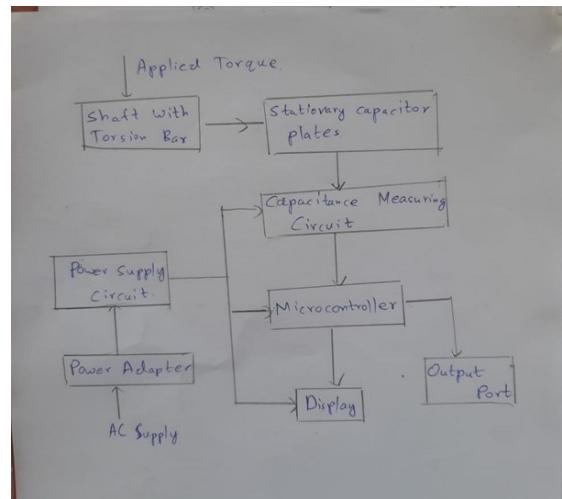
### Block Diagram

The system converts capacitance to voltage, processes it through a signal conditioning circuit (amplify, filter, noise reduction), and uses an A/D converter and MCU for torque calculation, displayed on a screen. USB torque data output and wireless communication enhance flexibility.

## 6.5 Selected Design previously



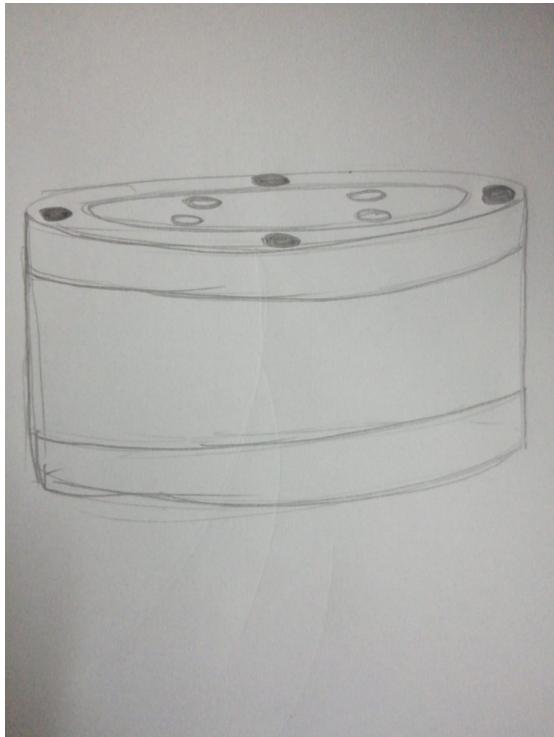
(a) Enclosure and Shaft Design



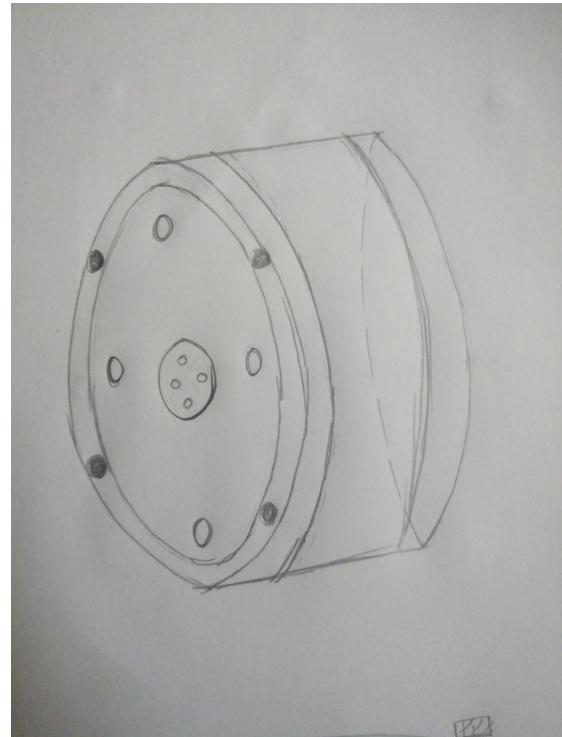
(b) Block Diagram

Figure 9: Final Selected Design

## 6.6 Selected Design Final



(a) View 01



(b) View 02

Figure 10: Final Selected Design

## **Enclosure Design**

The semi-cylindrical enclosure with a flat base and mounting feet ensures stability and easy integration. The compact design is practical, but a non-conductive material is essential to prevent interference with capacitance measurement.

## **Shaft Design**

The shaft with a torsion bar, as shown in the block diagram, transmits torque, causing deformation between stationary capacitor plates. Incorporating a high-permittivity dielectric could enhance sensitivity.

## **Block Diagram**

Torque applied to the shaft alters capacitance, measured by a circuit, processed by a microcontroller, and displayed. A power supply circuit with an adapter ensures reliable operation, and an output port allows data transfer. The setup is straightforward and effective.

## 7 Evaluation of the Designs

| Design         | User Need          | Design 01 | Design 02 | Design 03 | Design 04 |
|----------------|--------------------|-----------|-----------|-----------|-----------|
| Enclosure      | Ergonomics         | 6         | 8         | 8         | 6         |
|                | Durability         | 6         | 6         | 6         | 9         |
|                | Size & Weight      | 7         | 8         | 5         | 7         |
|                | Manufacturability  | 8         | 7         | 8         | 6         |
|                | Robustness         | 6         | 6         | 7         | 6         |
|                | Cost Effectiveness | 8         | 9         | 6         | 8         |
| Block Diagram  | Accuracy           | 7         | 7         | 7         | 8         |
|                | Signal Integrity   | 6         | 7         | 8         | 5         |
|                | Cost Effectiveness | 7         | 8         | 5         | 7         |
|                | Ease of Use        | 8         | 7         | 7         | 8         |
|                | Power Efficiency   | 9         | 7         | 6         | 7         |
|                | Scalability        | 7         | 7         | 8         | 6         |
| <b>Overall</b> |                    | 85        | 87        | 81        | 83        |

Table 2: Evaluation Table for Design Aspects

## 8 Capacitance and CDC Requirements Evaluations

### 8.1 Capacitance Calculation

Area of Dielectric =  $\pi (S^2 - 2^2) \times \frac{1}{4} \text{ m}$   
at 0 Nm

Area of Air at 0 Nm =  $\pi (21) \times \frac{3}{4} \text{ m}$

Dielectric constant = 4.3 [FR 4]

Capacitance of Dielectric =  $A \frac{(4.3) \times \epsilon_0}{d}$

$$= \frac{\pi (21)}{100^2} \times \frac{1}{4} \times \frac{4.3 \times 8.854 \times 10^{-12}}{8 \times 10^{-3}}$$

$$= 2.85 \times 10^{-12} \text{ F}$$

$$= 2.85 \text{ pF}$$

Figure 11: Area and Capacitance Calculation

## 8.2 Change of Capacitance

$$\begin{aligned}
 \text{Capacitance of Air} &= \frac{\pi(21)3}{100^2 \times 4} \times \frac{8.854 \times 10^{-12}}{8 \times 10^{-3}} \\
 &= 5.476 \text{ pF} \\
 \text{Total} &= 13.326 \text{ pF} \\
 \text{Rotation for } 1 \text{ Nm} &= 0.267^\circ \\
 \text{Change of Area} &= \frac{\pi(21)}{100^2} \times \frac{0.267 \times 20}{360} \text{ } \textcircled{o} \text{ } \underset{\text{in metal}}{\overset{\text{20 slots}}{\text{}}} \\
 \text{Change in Capacitance} &= \frac{\pi(21)}{100^2} \times \frac{0.267 \times 20 \times (4.3 - 1) \times 8.854 \times 10^{-12}}{360} \\
 &= 357.4 \text{ fF}
 \end{aligned}$$

Figure 12: Capacitance calculation

## 8.3 CDC Calculations

$$\begin{aligned}
 \text{FCD 2212} \\
 \text{Conversion time} &= \frac{15}{1000} = 1 \text{ ms.} \\
 t_{cx} &= \frac{CH_x - R_{\text{Count}} \times 16 + 14}{f_{\text{ref}}} \\
 1 \times 10^{-3} &= \frac{CH_x - R_{\text{Count}} \times 16 + 14}{40 \text{ MHz}} \\
 R_{\text{Count}} &\approx \frac{40 \times 10^6 \times 10^{-3}}{16} = 2500 \\
 0.3 \text{ fF at } 100 \text{ sps} &\text{ is given. noise} \\
 100 \text{ sps} \rightarrow t_{cx} &= 10 \text{ ms} \\
 R_{\text{Count}} &= \frac{40 \times 10^6 \times 10^{-3}}{16} = 25000
 \end{aligned}$$

Figure 13: CDC calculation(1)

## 9 CDC Evaluation

The requirements for choosing a capacitance-to-digital converter (CDC) were:

- Resolution – Able to measure few femto Farads of capacitance change.
- Sampling frequency – 1000 samples/second
- Range –  $\pm 360 \text{ fF}$

|                            | AD7746 | AD7150 | FDC1004 | PCAP04 | FDC2114 |
|----------------------------|--------|--------|---------|--------|---------|
| Frequency                  | 2      | 4      | 6       | 10     | 10      |
| Resolution                 | 9      | 6      | 7       | 8      | 6       |
| Range                      | 7      | 8      | 9       | 9      | 9       |
| Environmental Compensation | 9      | 6      | 7       | 8      | 8       |
| Price                      | 6      | 8      | 9       | 7      | 7       |
| Availability               | 10     | 7      | 9       | 8      | 8       |
| Total                      | 43     | 39     | 47      | 50     | 48      |

Figure 14: CDC Evaluation table

AD7746, AD7150, and FDC1004 could not support the 1000 Samples/second requirement and were therefore eliminated. Although the AD7746 had 4aF resolution, its sampling frequency was only 10Hz, which was well below the requirements. The final selection was between PCAP04 and FDC2114. Both satisfied the required sampling rate and capacitance range, but PCAP04 had better resolution at 1kHz.

## PCAP Qualities

- 156aF resolution at 1kHz
- $\pm 50\text{pF}$  range
- Temperature compensation



Figure 15: PCAP04 CDC

## 10 MCU Calculation

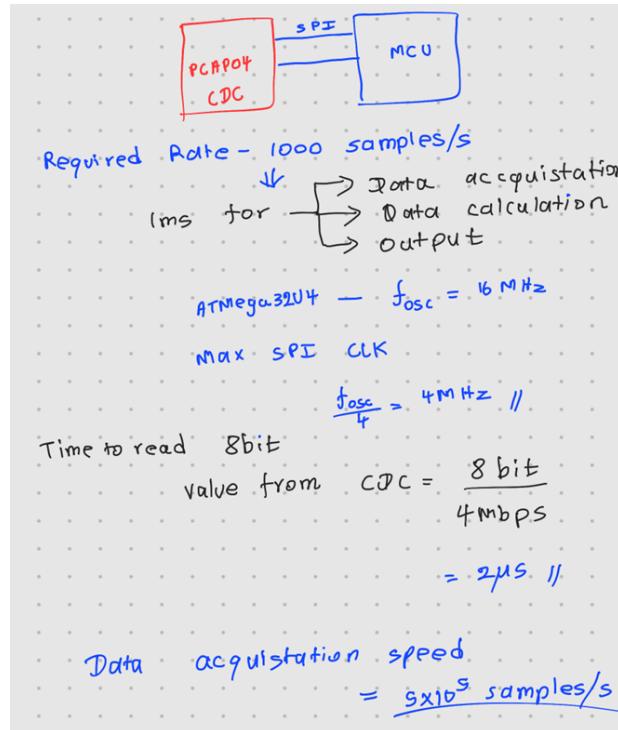


Figure 16: MCU calculation(1)

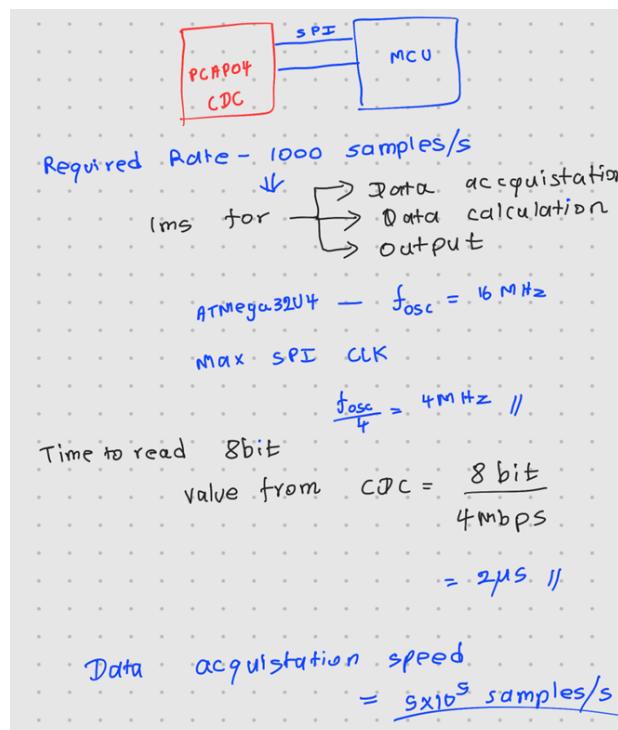


Figure 17: MCU calculation(2)

## 11 MCU Evaluation

### Comparison Table

| MCU                 | ATmega32U4 | ATmega32U2 | ATmega64M1 | PIC18F46J50 | EFM8UB20  |
|---------------------|------------|------------|------------|-------------|-----------|
| Performance         | 8          | 7          | 10         | 10          | 9         |
| Size (Compactness)  | 8          | 9          | 9          | 8           | 9         |
| USB Capability      | 10         | 10         | 10         | 10          | 10        |
| EMC/EMI Robustness  | 7          | 7          | 8          | 7           | 9         |
| Ease of Development | 10         | 9          | 8          | 7           | 7         |
| Documentation       | 9          | 8          | 7          | 8           | 7         |
| Availability        | 10         | 10         | 8          | 9           | 7         |
| Cost                | 7          | 8          | 6          | 7           | 9         |
| <b>Total</b>        | <b>69</b>  | <b>68</b>  | <b>66</b>  | <b>66</b>   | <b>67</b> |

### Selection Criteria

- Native USB support
- Enough performance for 1kHz sample processing
- Ease of development
- EMC/EMI resilience

### Chosen MCU – ATmega32U4

#### Specifications:

- 16MHz / 32KB Flash / 2.5KB SRAM
- Compact – 44 pins
- Microchip Studio free IDE / beginner friendly
- Internal crystal oscillator / brownout protection

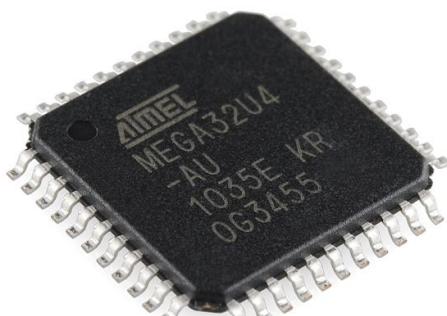


Figure 18: ATMega32U4

## 12 Dielectric Material Evaluation

### Desired Specifications

- Higher dielectric constant
- Good strength
- Ease of machining
- Lower cost

|                     | PTEF (Teflon) | Polyimide (Kapton) | Alumina Ceramic (Al <sub>2</sub> O <sub>3</sub> ) | FR4 (Glass Epoxy) | Polycarbonate |
|---------------------|---------------|--------------------|---|-------------------|---------------|
| Dielectric Constant | 7             | 9                  | 10  | 8                 | 6             |
| Flexural Strength   | 4             | 7                  | 9   | 10                | 5             |
| Ease of Machining   | 8             | 6                  | 3   | 7                 | 9             |
| Stability           | 9             | 8                  | 10  | 8                 | 7             |
| Cost                | 6             | 4                  | 3   | 9                 | 10            |
| Total               | 34            | 34                 | 35  | 42                | 37            |

Figure 19: Evaluation Table

Al<sub>2</sub>O<sub>3</sub> was initially considered due to its high dielectric constant and excellent stability. However, it is brittle and requires diamond cutting/laser sintering, making it unsuitable for the project.

### Chosen Material – FR4 (Glass Epoxy)

#### Properties:

- Dielectric constant – Around 4.5
- Shear Strength – Approx. 25,000 psi
- Flexural Strength – Approx. 60,000 psi
- Machinability – CNC milling, laser cutting, water jet cutting
- Stability – 140°C / Water Absorption 0.1%



Figure 20: FR4 - Epoxy Glass

## 13 Shaft Design

The shaft for mounting metal/dielectric disks was designed and simulated in SolidWorks. Several shaft designs were explored with different geometries and materials.

### Design Requirements

- High deformation at 1Nm – measurable capacitance difference
- Must not exceed the shear stress of material at 5Nm

### Design Iterations

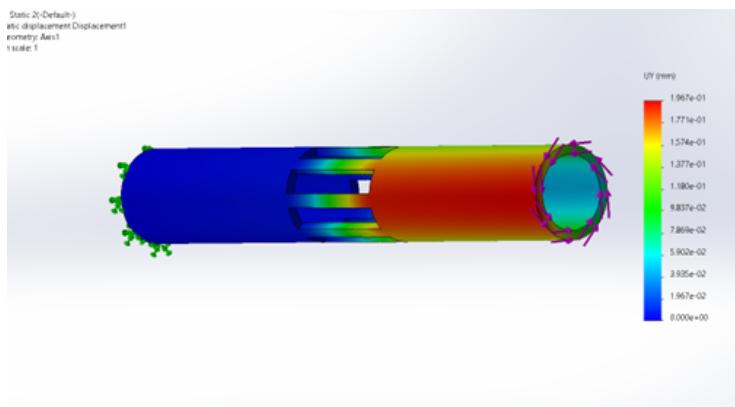


Figure 21: Short shaft – similar to the reference design

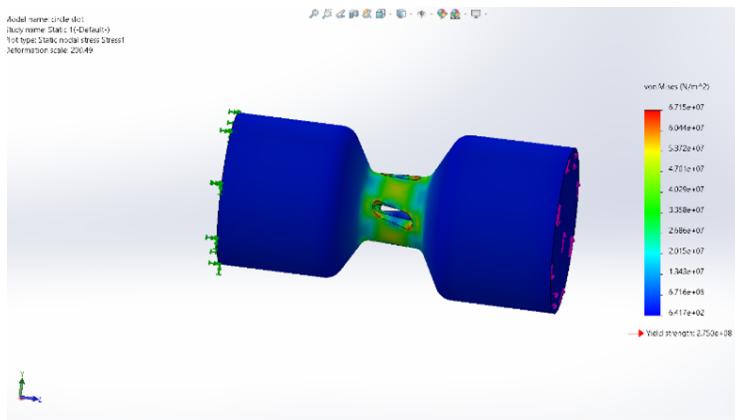


Figure 22: Shaft with pill-shaped cutouts

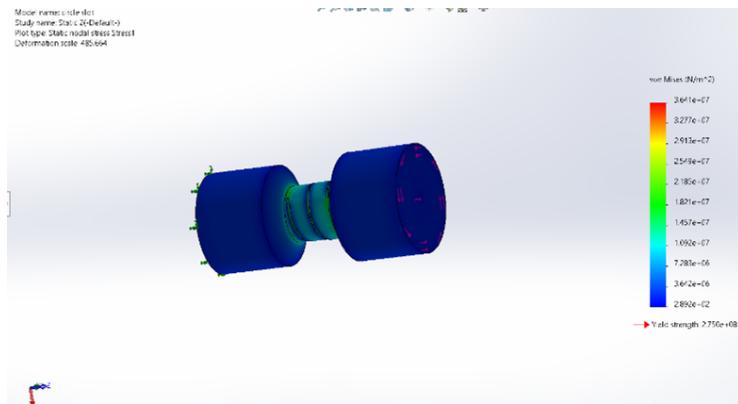


Figure 23: Shaft with helical groove

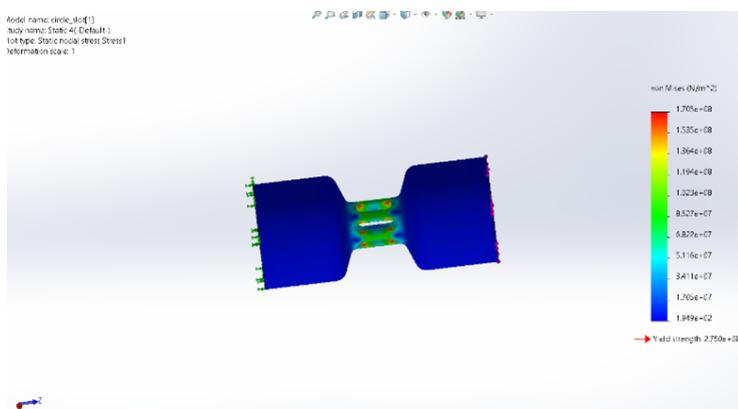


Figure 24: Pill-shaped cutouts + fillets

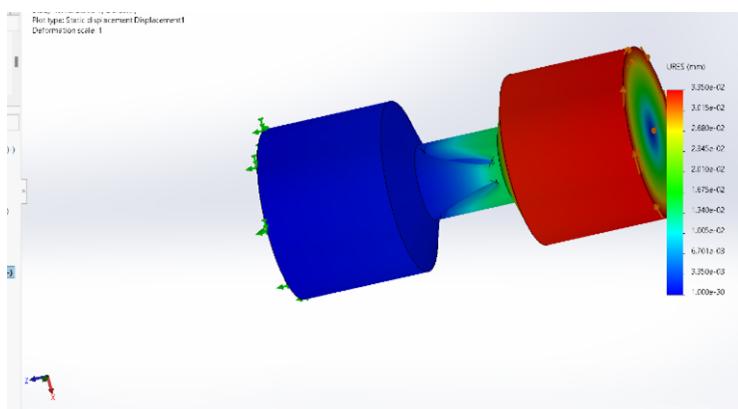


Figure 25: Angled pill-shaped cutouts + fillets

All versions with cutouts exceeded the shear stress limit at 5Nm. The final design was a shaft with no cutouts and a reduced diameter.

## Final Shaft Design

- Diameter at ends – 1.7 cm
- Diameter at middle – 0.6 cm
- Thickness – 2 mm
- Deformable region length – 1.4 cm
- Material – Aluminum alloy 6061-T6

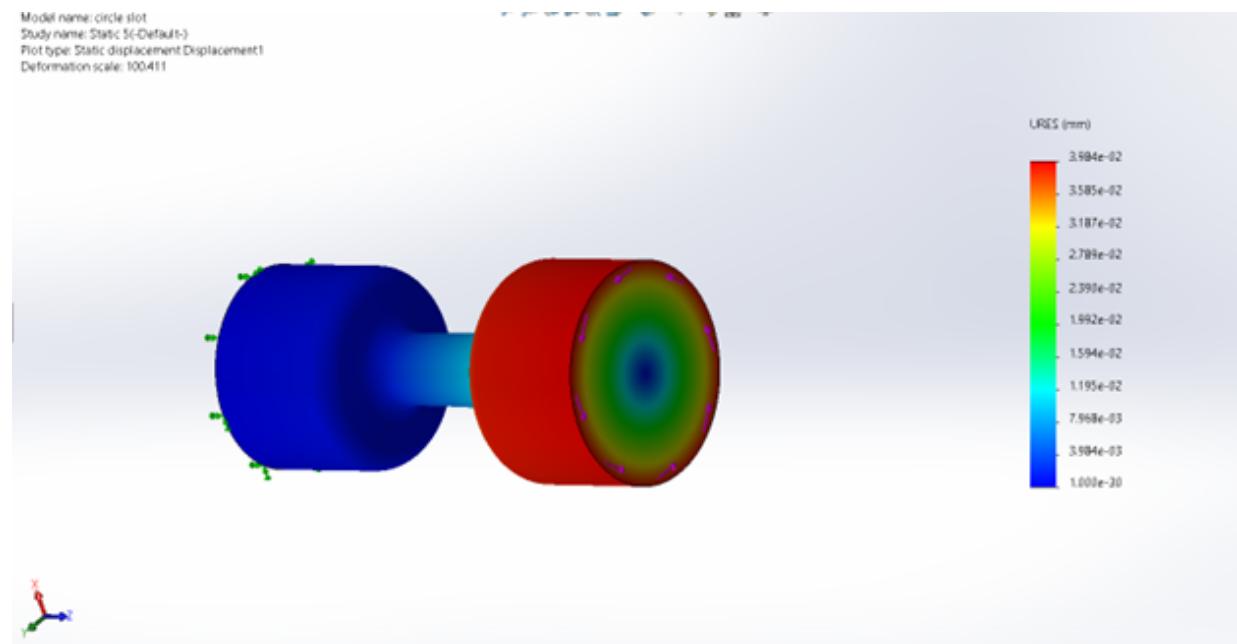


Figure 26: Final Shaft

### Performance:

- Deformation at 1Nm –  $3.984 \times 10^{-4}$  mm
- Angle of rotation – 0.2680 degrees
- Change in capacitance – 357.4 fF (measurable with 156aF resolution of PCAP04)

## 14 Solidworks 3D Design

### 14.1 Initial Design - Version 01

The initial design was developed with these key characteristics:

- **Enclosure Structure:**

- Two-part post-box shaped aluminum housing (front & backcovers)
- Included mounting points for PCB and mechanical components
- Provided space for display and USB Integration

- **User Interface:**

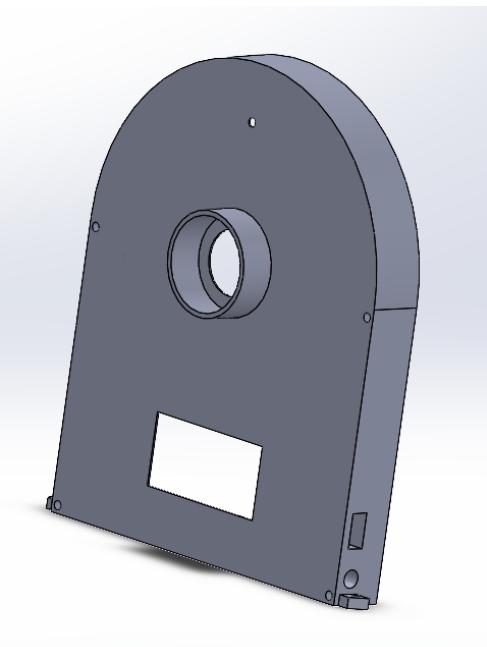
- Display cutout on top surface
- USB port for data/power on side panel

- **Internal Components:**

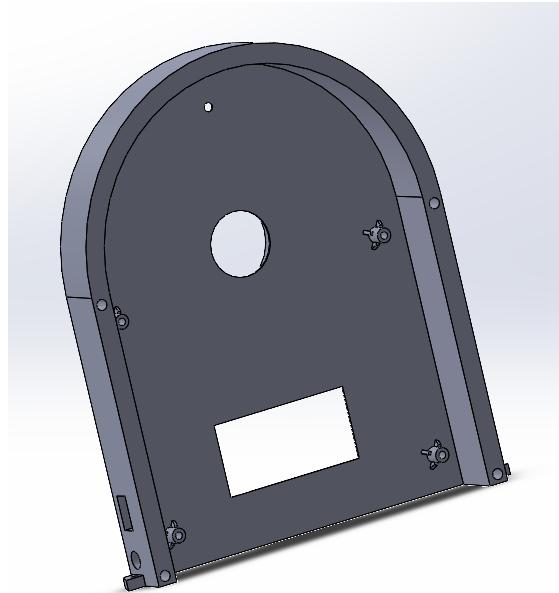
- Central shaft with bearing supports
- Stacked disk configuration (3 metal + 1 dielectric)
- Custom holders for precise disk alignment

#### 14.1.1 Outer Enclosure

Frontside view



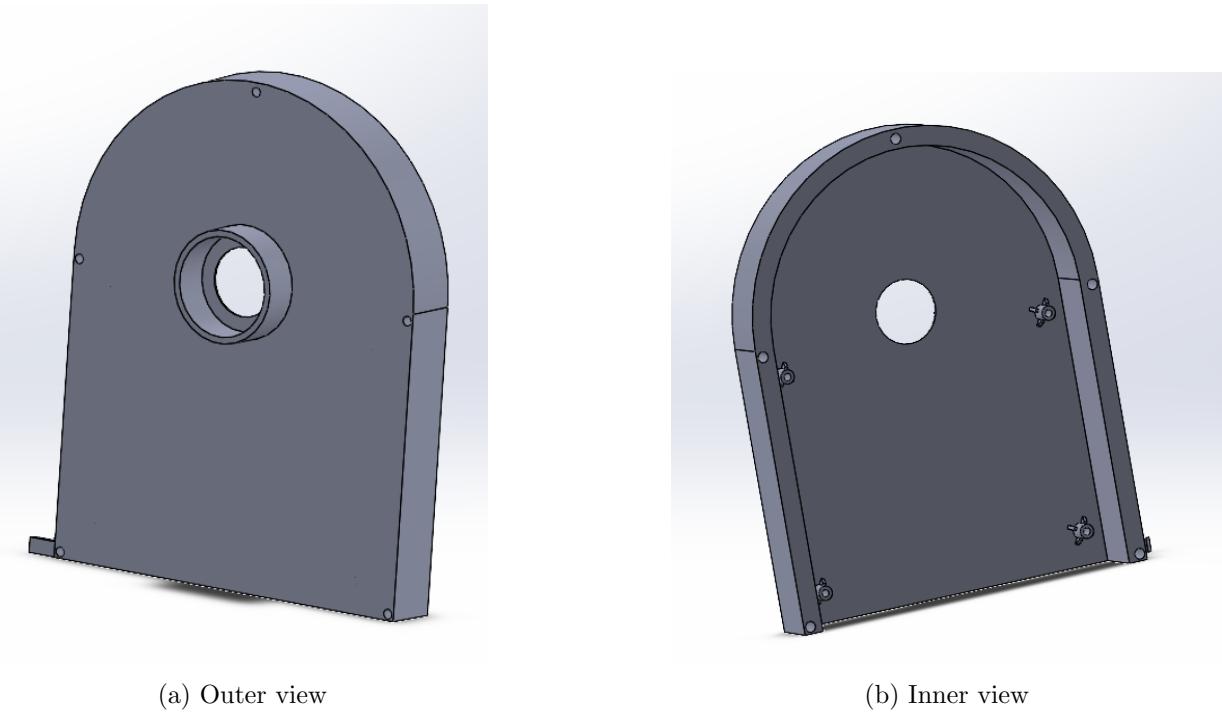
(a) Outer view



(b) Inner view

Figure 27: Front Half

**Backside view**



(a) Outer view

(b) Inner view

Figure 28: Backside Half

**Bottom Part**

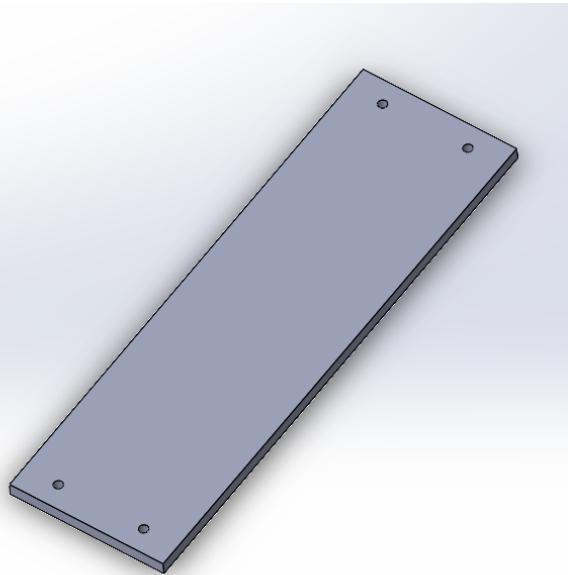


Figure 29: Bottom Part

#### 14.1.2 Inner Parts

##### Disks

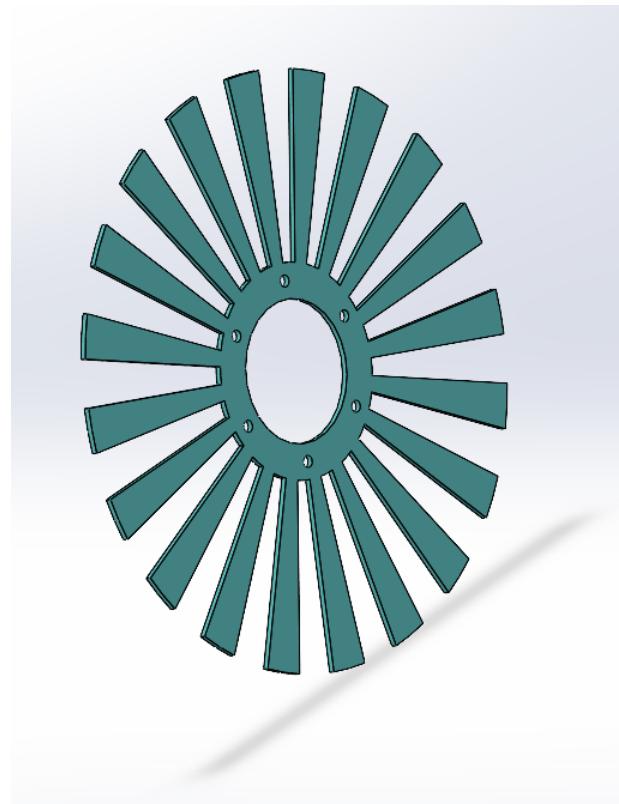


Figure 30: Dielectric Disk

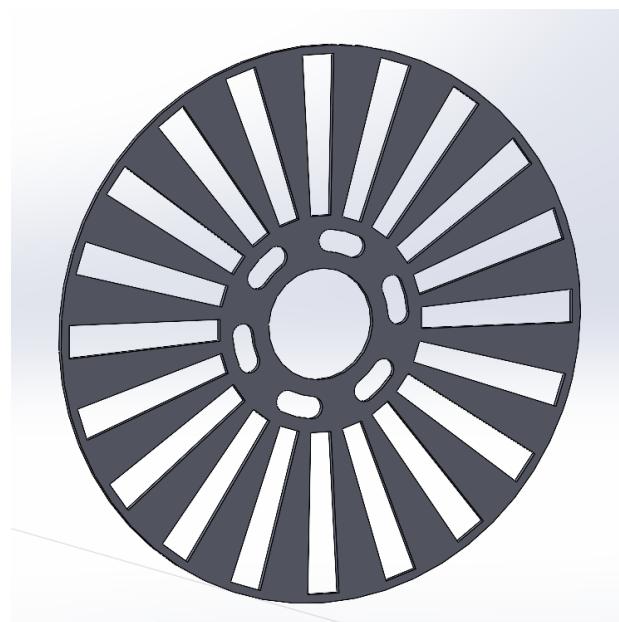
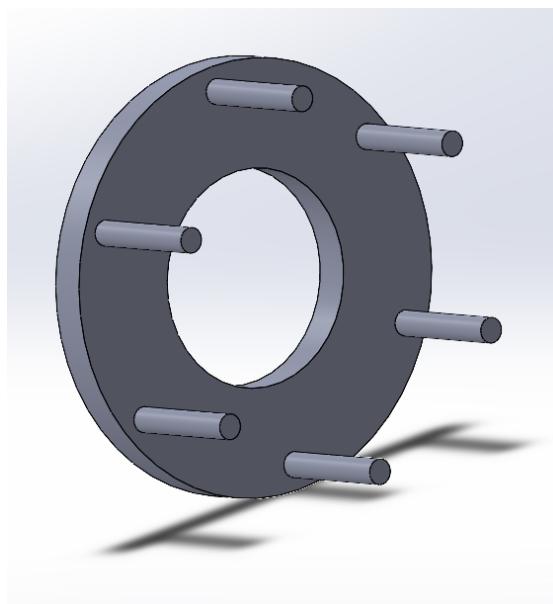
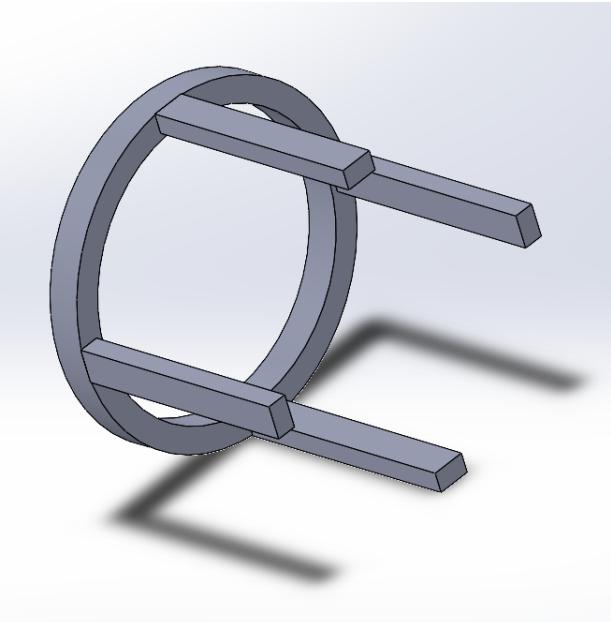


Figure 31: Metal Disk

## Connecting Parts



(a) Dielectric Holder



(b) Metal Plate Holder

Figure 32: Connecting Holders

## Shaft

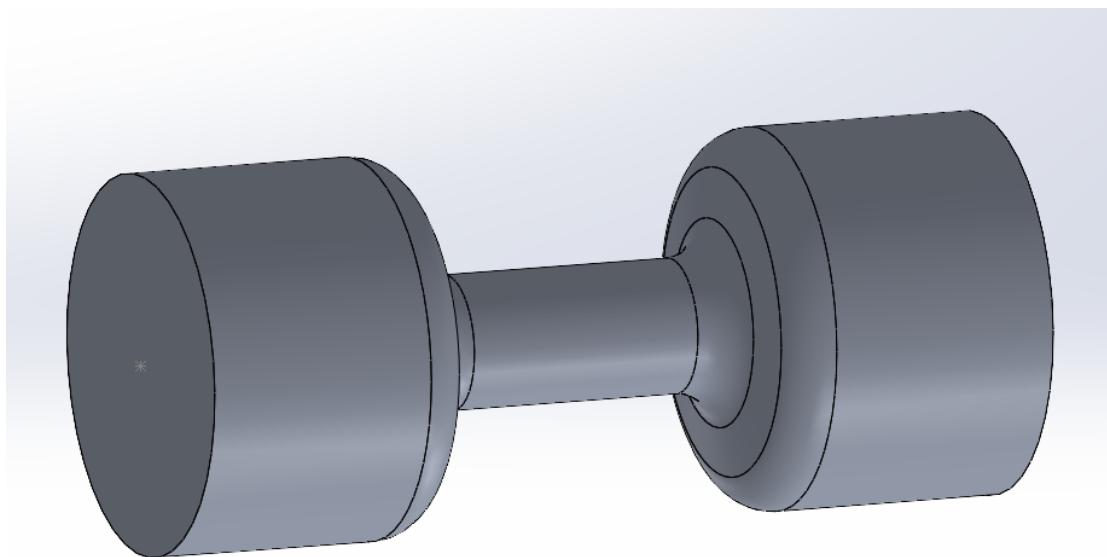


Figure 33: Shaft

#### 14.1.3 Final Assembly

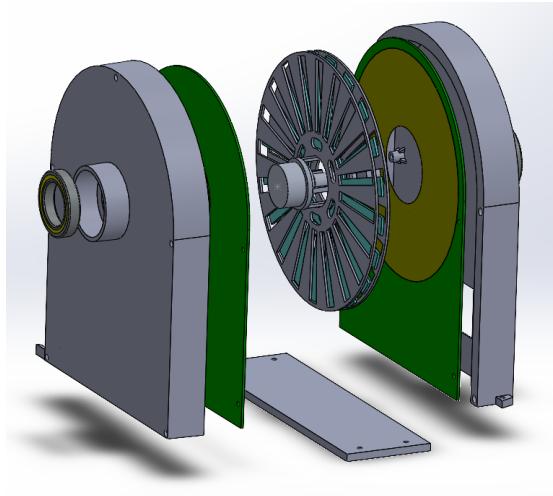


Figure 34: Backside View

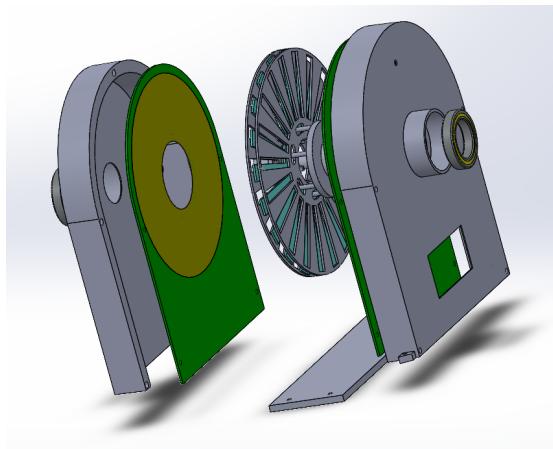


Figure 35: Frontside View

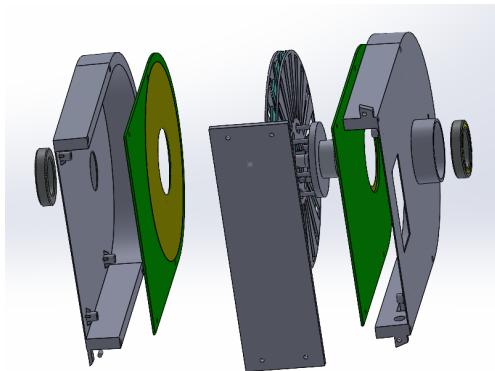


Figure 36: Bottom view

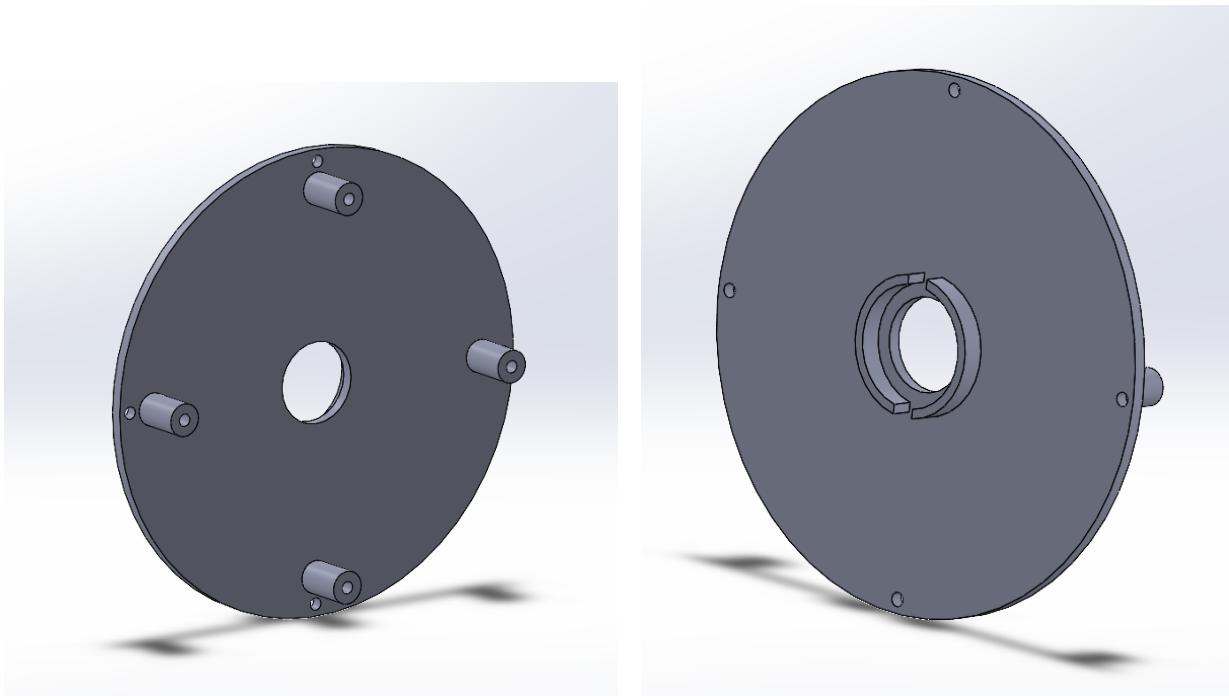
## 14.2 Final Design - Version 02

After consultation with Sir and benchmarking and aligning with our reference Design I-PEX torque sensors, these modifications were implemented:

- **Form Factor Changes:**
  - Shifted to cylindrical profile
  - Single-piece extruded aluminum body
  - Removed all flat surfaces
  - Shaft length and diameters are modified
  - Put holes in the shaft ends to connect with external body (eg:- Robot arm)
- **Simplified Interface:**
  - Eliminated display to reduce complexity
  - Single USB port serial output
- **Improved Mechanical Features:**
  - Unified shaft-bearing-disk assembly
  - Preloaded angular contact bearings for better axial stability
  - Gold-plated contacts for capacitive sensing
- **Common Features Maintained:**
  - Core capacitive sensing principle (inner Disks and Disk Holders Design)
  - Identical disk materials and spacing
  - Same torque measurement range (0-1Nm)
- **Key Improvements:**
  - Better alignment with industry standards
  - 40% reduction in production cost
  - More robust shaft coupling design

#### 14.2.1 Outer Enclosure

Front and back half



(a) Frontside

(b) Backside

Figure 37: Enclosure caps

#### Cylindrical Body

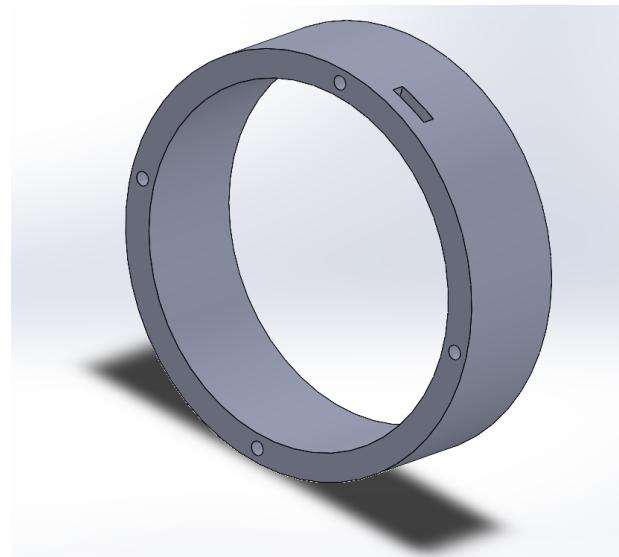


Figure 38: Cylinder Enclosure

#### 14.2.2 Shaft

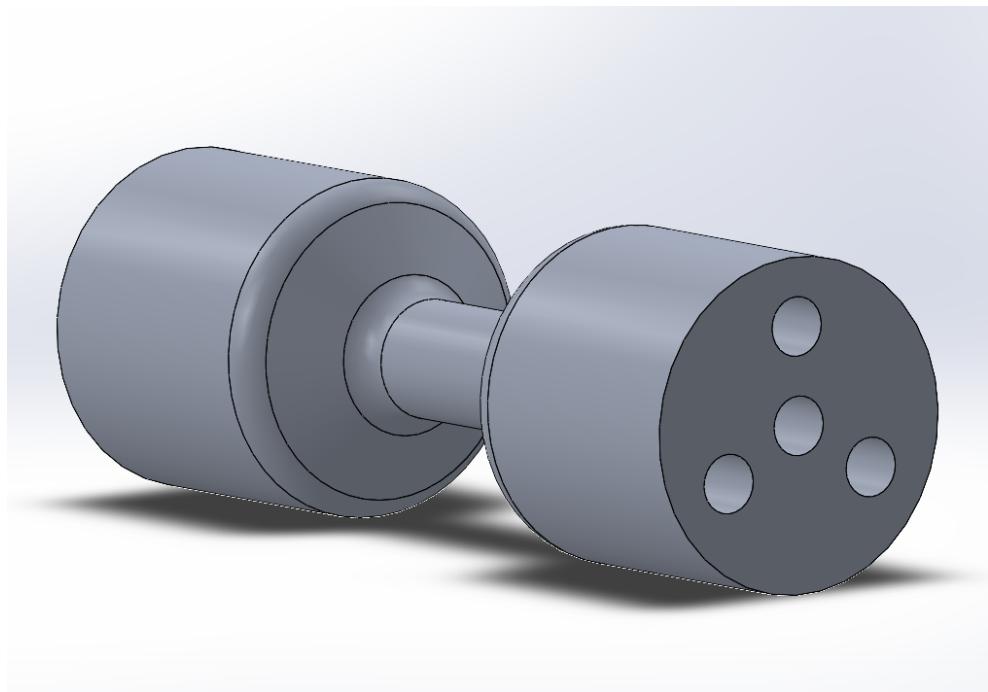
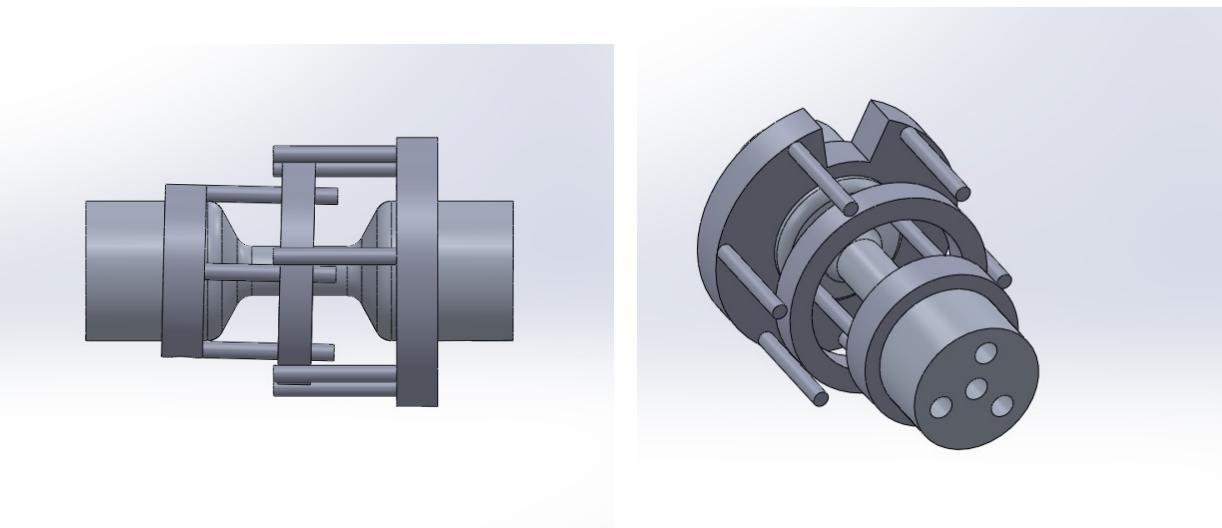


Figure 39: Final Shaft

#### 14.2.3 Shaft and holders with modified Dimensions



(a) Side View

(b) Angle view

Figure 40: Internal assembly of Shaft and Holders

**14.2.4 Full assembly**  
**Full Product Overview**

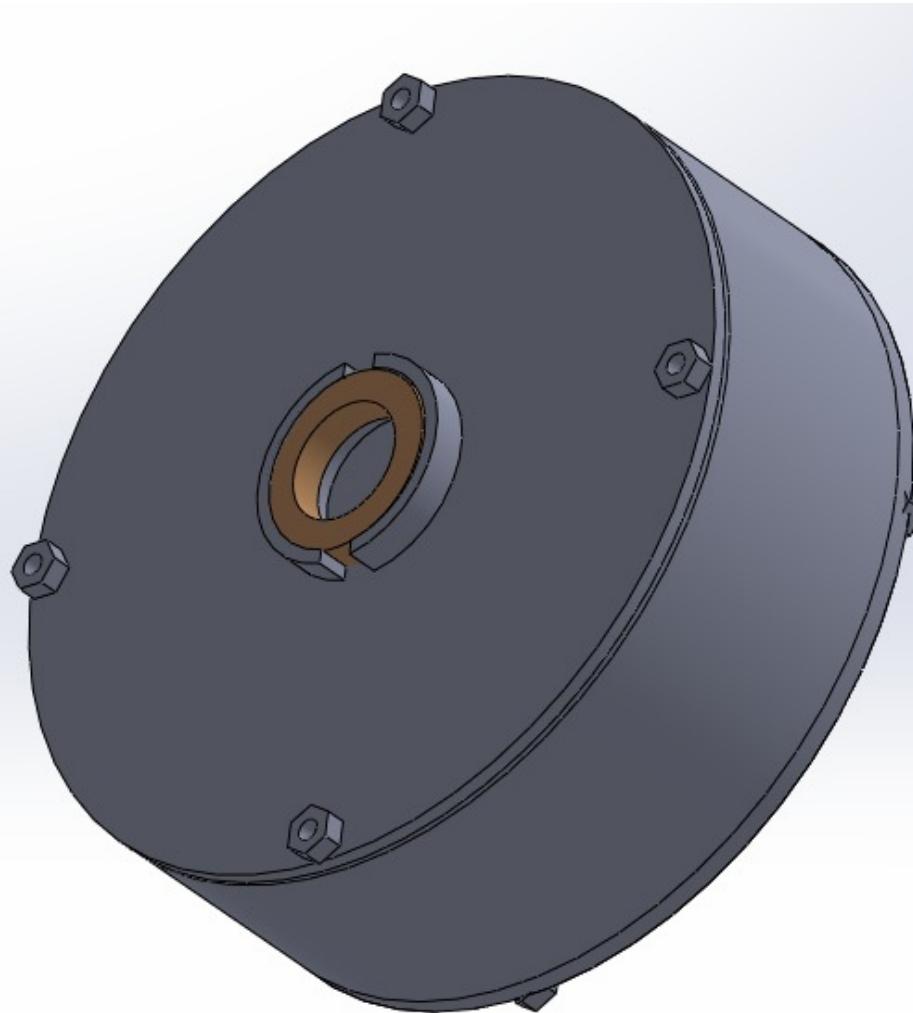


Figure 41: Full Closed view

**Exploded view with internal positions**

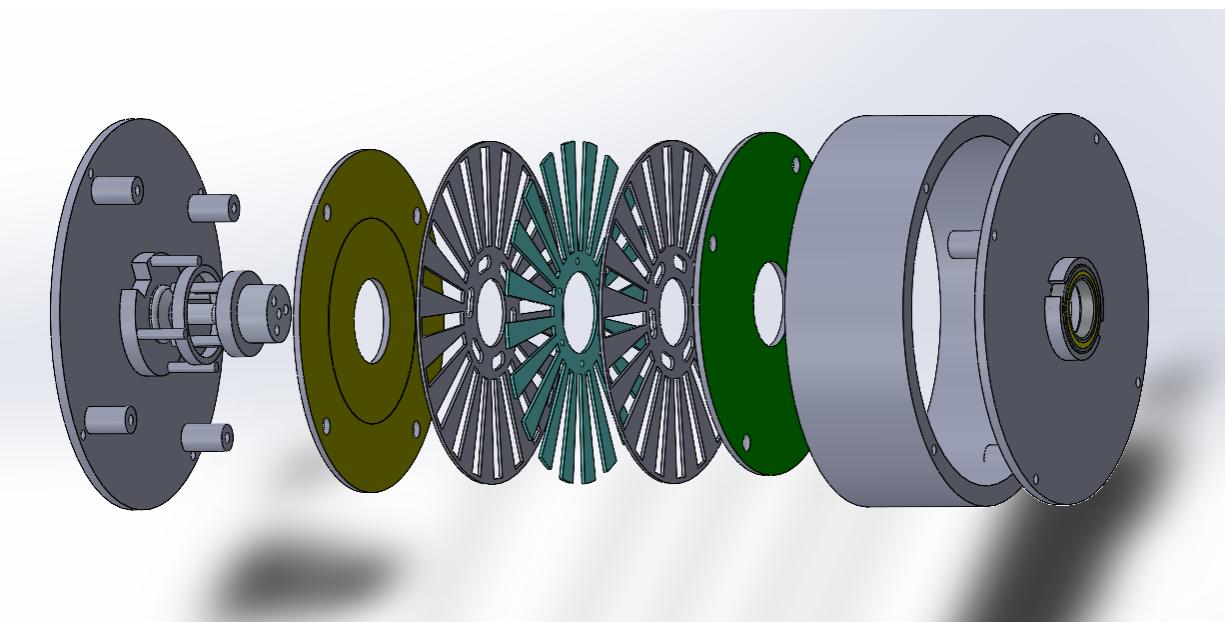


Figure 42: Exploded view 01

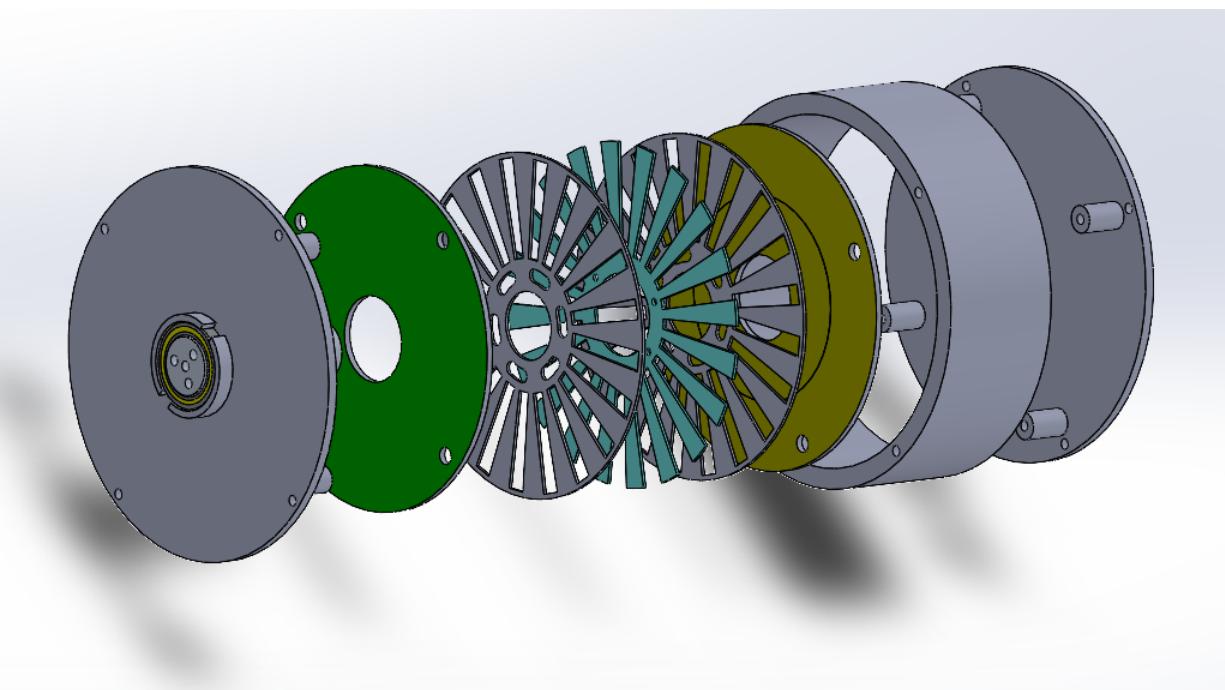
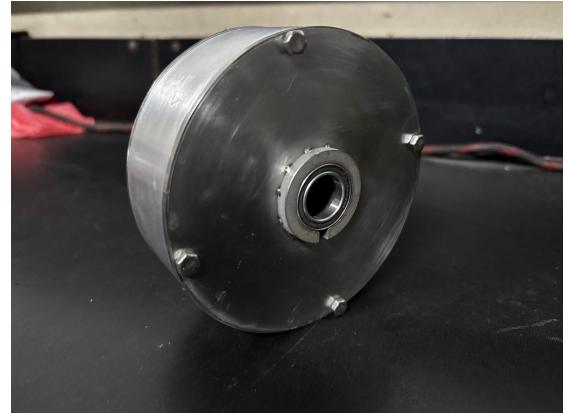


Figure 43: Exploded view 02

## 15 Actual Product (Physical)



(a) Side View



(b) Angle view

Figure 44: Actual Product Outer look



(a) Side View



(b) Front cap with Bearings

Figure 45: Enclosure Outer look



Figure 46: Dielectric and Metal holders



(a) Side View



(b) Front cap with Bearings

Figure 47: Inner Disks



(a) Side View



(b) Front cap with Bearings

Figure 48: Shaft

# 16 Schematic Circuit Design

## 16.1 MCU Circuit

- Core Components:

- ATmega32U4 microcontroller
- Key functions:
  - Reads capacitance via SPI
  - Computes torque using calibration equation
  - Manages USB communication

- Power Management:

- 5x  $V_{CC}$  pins with decoupling capacitors
- $AVCC$  pin filtered via ferrite bead

- Clock: ECS-8FMX-160-TR 16MHz oscillator for USB timing
- UI: Reset button, 3x LEDs (USB/SPI/status)

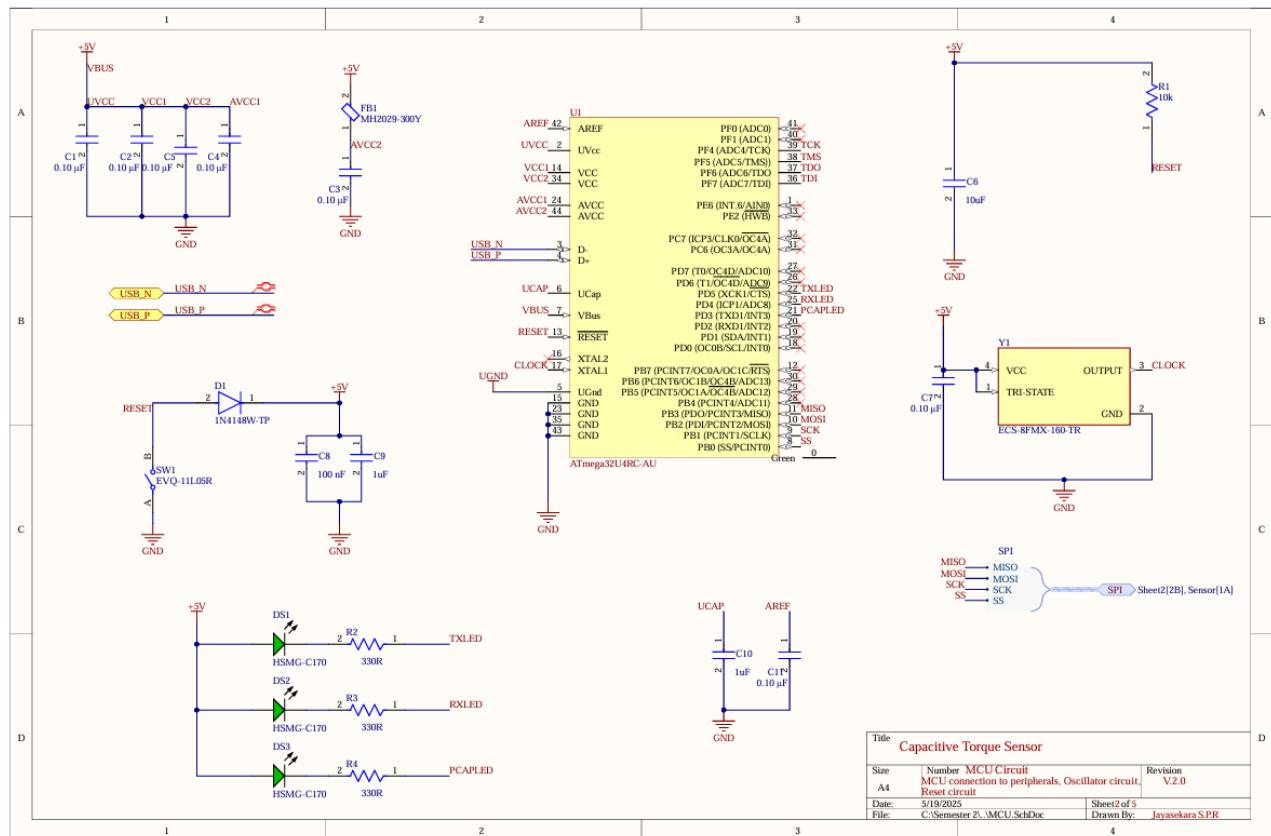


Figure 49: MCU Schematic

## 16.2 USB Circuit

- Provides **data transmission** and **power supply** (+5V via VBUS).
- **ESD Protection:**
  - +D/-D lines connected to ground through **varistors**.
- **Grounding:**
  - USB ground (UGND) and main ground linked via **ferrite bead** for:
    - \* High-frequency noise filtering
    - \* Prevention of ground loops
- **Power Line Protection:**
  - Resettable fuse for overcurrent protection
  - Capacitor C12 for ripple smoothing
  - LED DS4 as power indicator

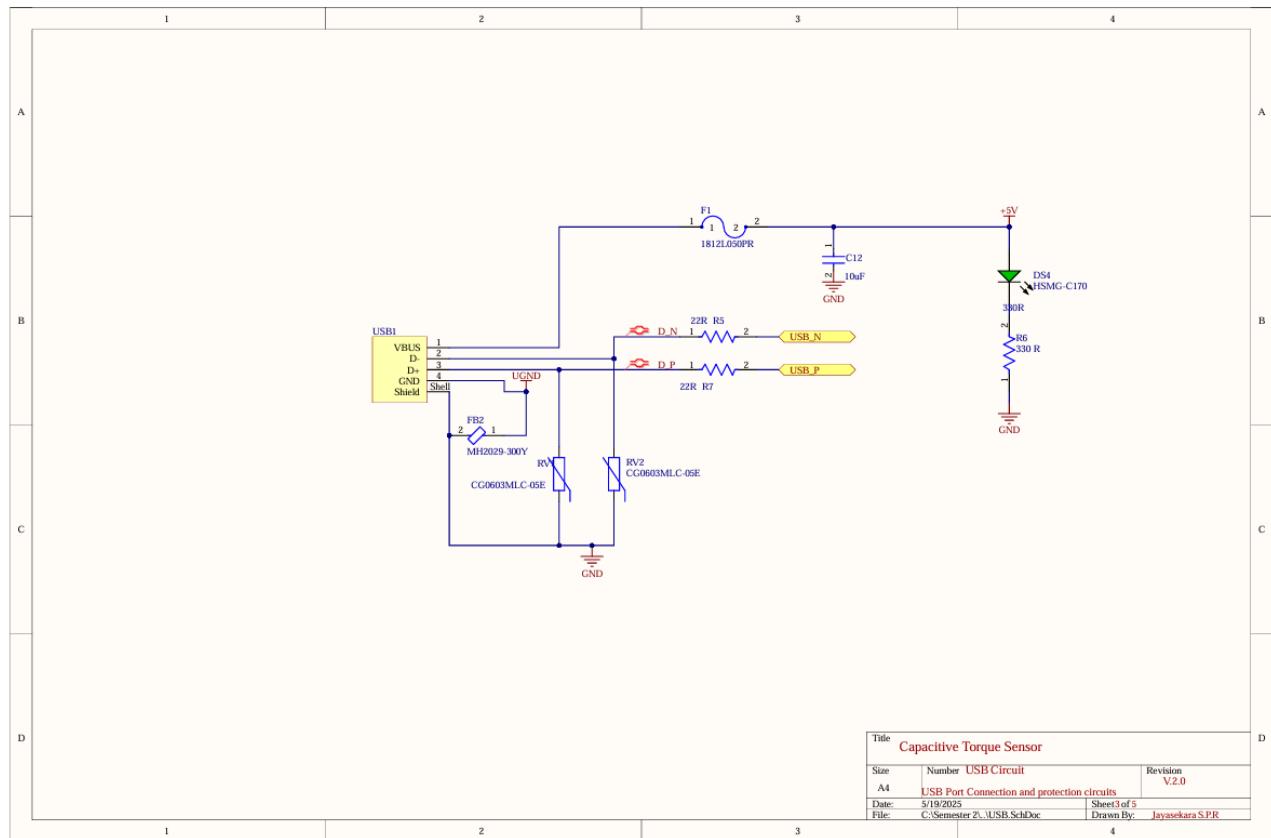


Figure 50: USB Schematic

### 16.3 Power Circuit

- Generates regulated voltages:
  - +3.3V and +1.8V for PCAP04 CDC
- Design Features:
  - Enable pins tied to  $V_{CC}$  for continuous operation
  - Input/output capacitors for:
    - \* High-frequency noise filtering
    - \* Ripple reduction

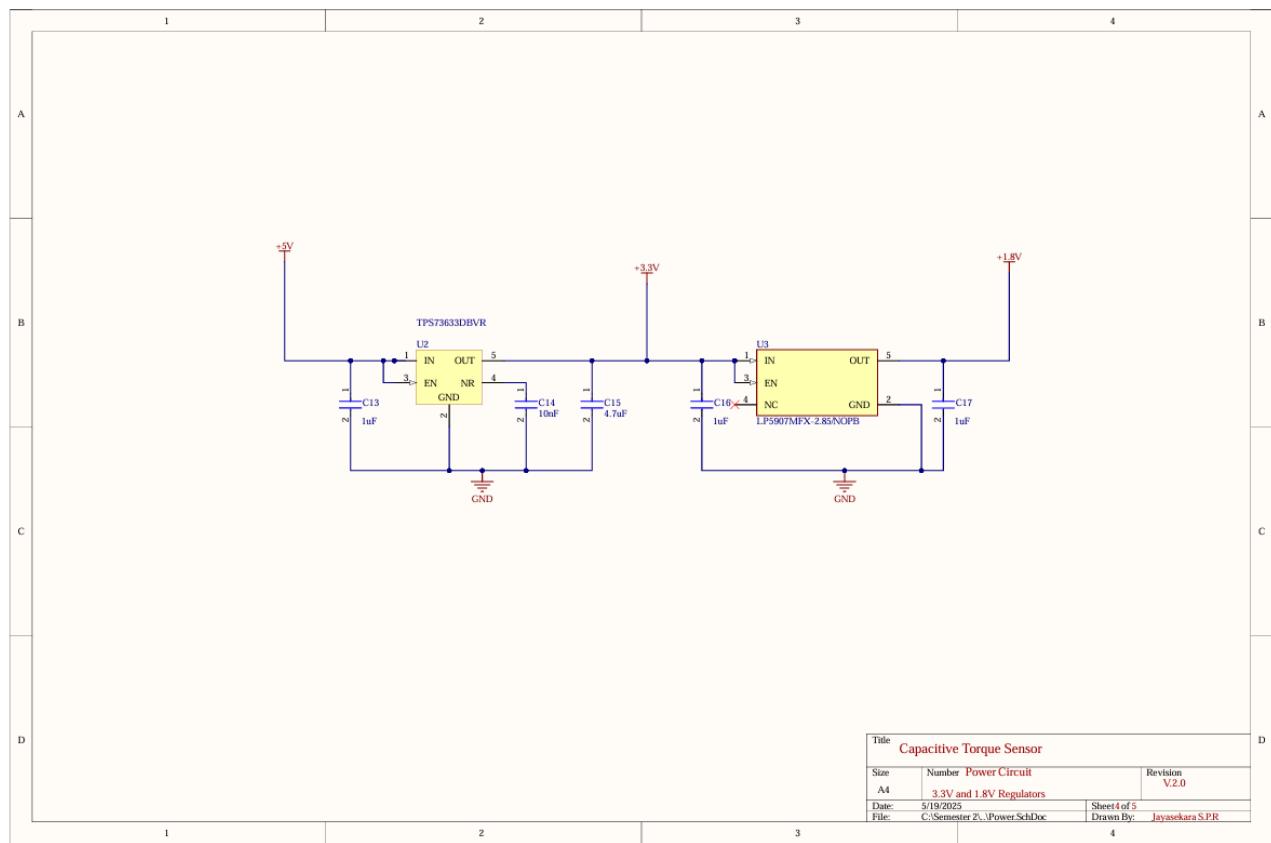


Figure 51: Power Supply Schematic

## 16.4 Sensor (CDC) Circuit

- Capacitance-to-Digital Converter (PCAP04):

- Powered by +3.3V (digital) and +1.8V (analog)
- PC1 pin connected to sensor plates via 2-wire JST connector
- Operates in **differential capacitance mode**
- SPI communication with MCU

- MOSFET Level Shifters:

- Converts MCU's +5V signals to +3.3V for CDC
- Replaced TXB0104PWR IC due to low drive current
- Used for SPI lines (SCK, MOSI, MISO, CS)

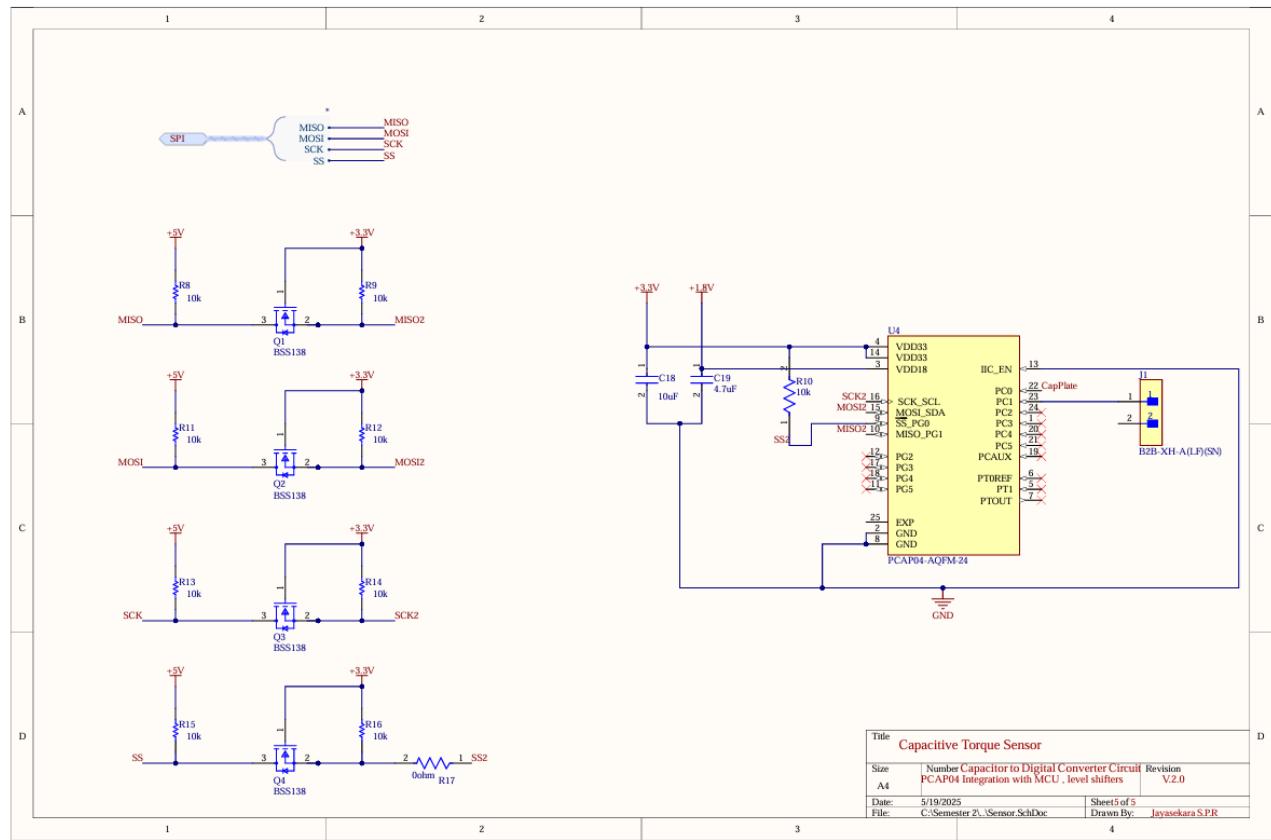


Figure 52: CDC Sensor Schematic

# 17 PCB Design

The two PCBs were designed using Altium Designer. The PCB serves two purposes in our product:

- Holds and routes components
- Acts as a capacitor plate for measuring capacitance

## 17.1 PCB Specifications

- Circular shape with a hole in middle for the shaft and disk holders
- Outer diameter: 10 cm and Inner diameter: 3.4 cm
- 4-layer stack-up:
  1. Signal Layer for component placement and routing
  2. Solid ground layer
  3. Power layer (+5V and +3.3V)
  4. Solid copper pour which acts as a capacitor plate

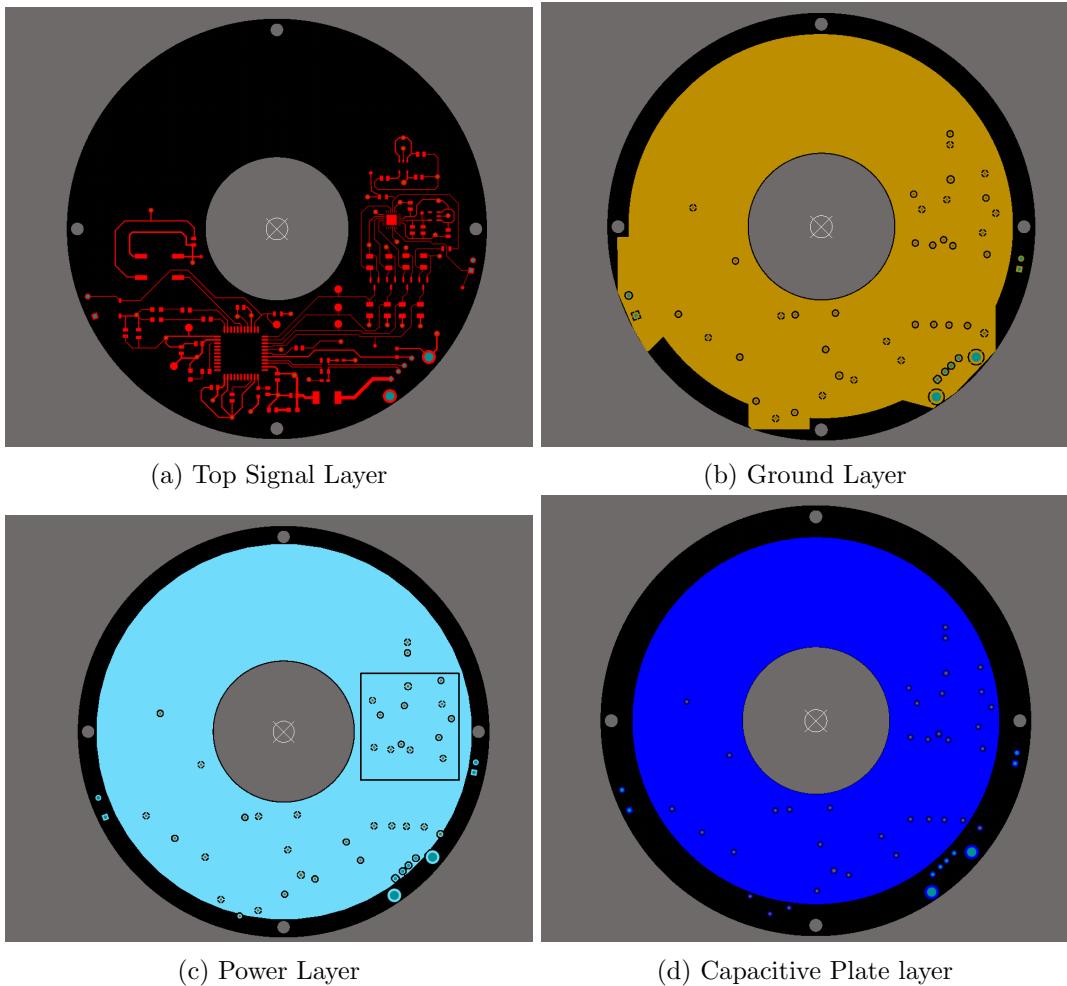


Figure 53: PCB Layers view

## **17.2 Noise Immunity Features**

The PCB incorporates ground and power planes to ensure noise immunity:

- Continuous ground plane acts as a shield, minimizing radiated emissions and reducing susceptibility to external noise
- Provides low impedance return path for signals (crucial for high-speed signals like USB)
- Power layer (+5V and +3.3V) creates natural parallel-plate capacitor with ground layer, providing distributed decoupling capacitance
- Ground plane (layer 2) provides isolation between routing layer and capacitive sensing plate, preventing noise coupling

## **17.3 Routing Considerations**

- Components tightly arranged to avoid long noise-prone traces
- Through-hole components placed near board edges to minimize effect on capacitance plate
- USB traces routed as differential pair (0.3mm width, 0.254mm gap) for 90 $\Omega$  impedance matching

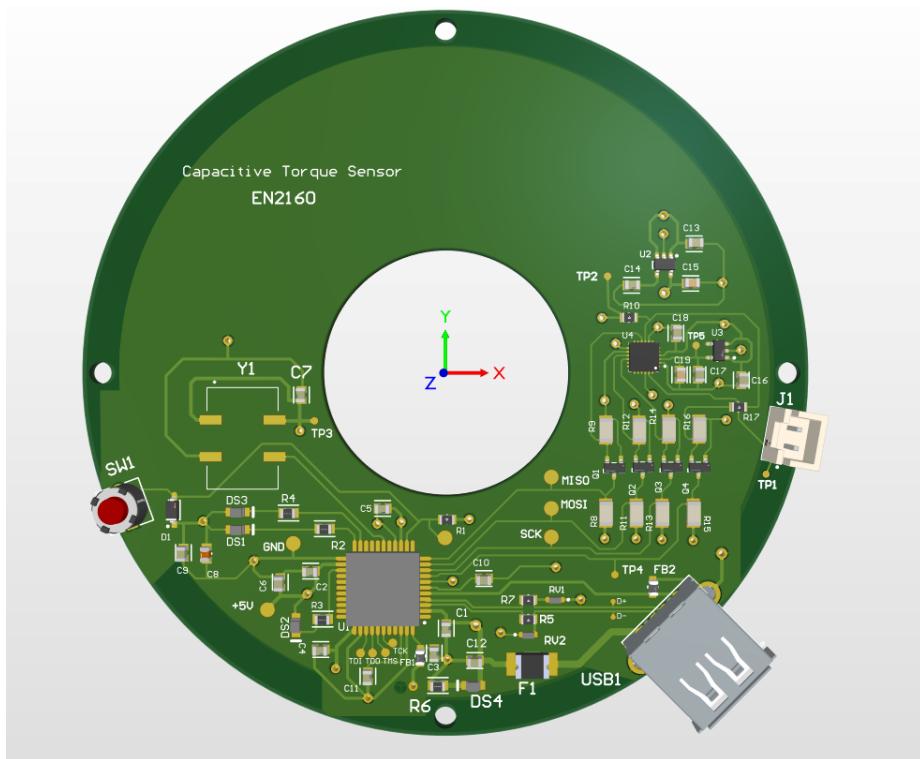


Figure 54: Front View

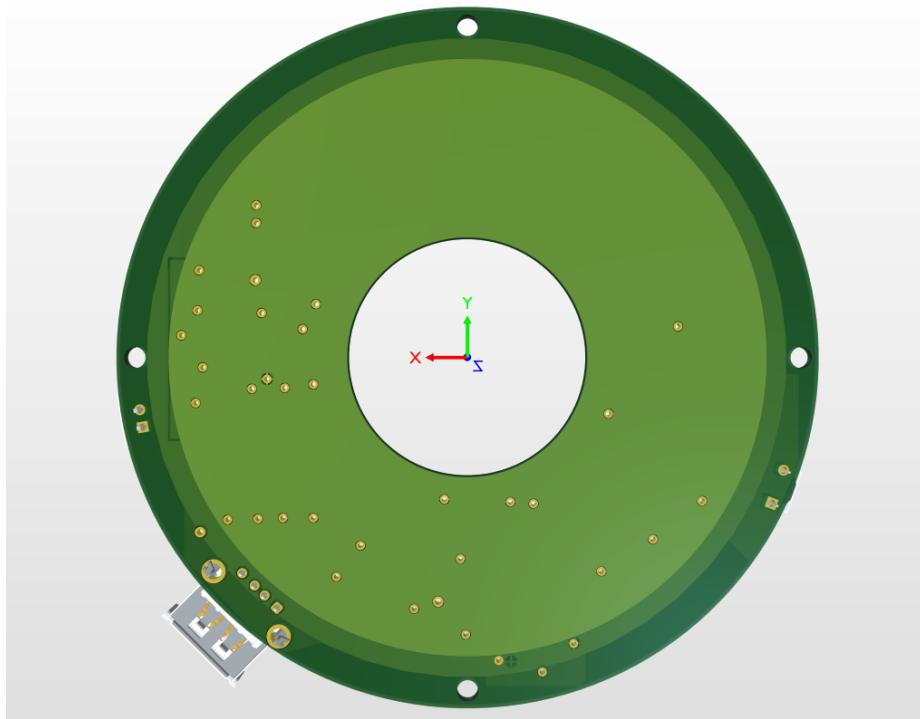


Figure 55: Backside View

## 18 Testing Procedure

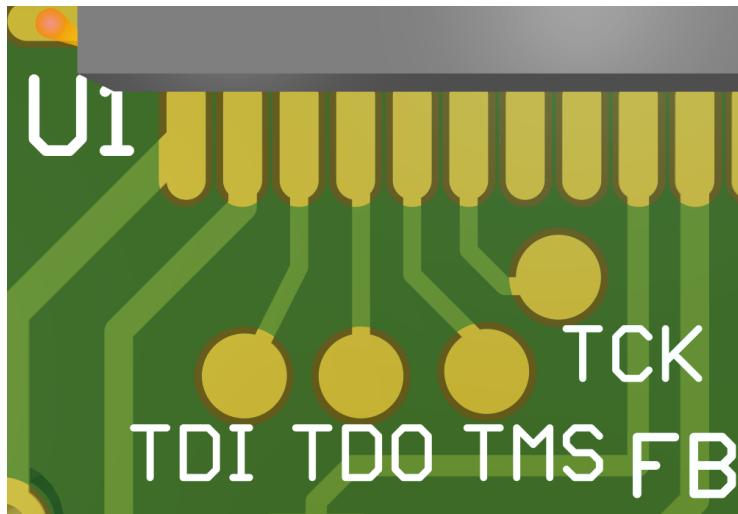


Figure 56: Test Points Implementation on PCB

After learning about proper test point implementation in our coursework, we enhanced our PCB design to include comprehensive testing capabilities. The evolution of our test point implementation occurred in two phases:

### 18.1 Initial Testing Implementation

The first PCB revision included basic test points primarily for power verification:

- Voltage test pads for regulator output validation
- Bootloader programming headers that doubled as general test points

### 18.2 Enhanced Testing Capabilities

Through further study of PCB testing methodologies, we added advanced test features:

- USB differential pair test points for signal integrity verification
- Full JTAG interface for the Atmega32U4 microcontroller

The JTAG test points (TDI, TDO, TMS, TCK) enable several critical testing procedures:

- **Interconnect Testing:** Verifying proper connections between components
- **Boundary Scan:** Testing PCB traces and solder joints
- **Programming/Debugging:** Allowing in-circuit firmware updates and debugging

This implementation allows us to perform comprehensive board validation, from basic power-on tests to advanced boundary scan testing, significantly improving our testing capabilities compared to the initial design.

## 19 Bill of Materials (BOM)

| Comment             | Designator                | Quantity | Unit Price (USD) | Total Price(USD) |
|---------------------|---------------------------|----------|------------------|------------------|
| C0805C104J8RACTU    | C1, C2, C3, C4, C5, C7, C | 7        | 0.127            | 0.889            |
| C0805C106K8PACTU    | C10, C12, C13, C16, C     | 8        | 0.556            | 4.448            |
| CC0805KRX7R7BB104   | C8                        | 1        | 0.167            | 0.167            |
| 10nF                | C14                       | 1        | 0.165            | 0.165            |
| 4.7uF               | C15, C19                  | 2        | 0.55             | 1.1              |
| 1N4148W-TP          | D1                        | 1        | 0.03             | 0.03             |
| HSMG-C170           | DS1, DS2, DS3, DS4        | 4        | 0.04             | 0.16             |
| 1812L050PR          | F1                        | 1        | 0.4              | 0.4              |
| MH2029-300Y         | FB1, FB2                  | 2        | 0.1              | 0.2              |
| B2B-XH-A(LF)(SN)    | J1                        | 1        | 0.3              | 0.3              |
| BSS138              | Q1, Q2, Q3, Q4            | 4        | 0.03             | 0.12             |
| CRCW080522R0FKEA    | R1, R5, R7, R10, R17      | 5        | 0.104            | 0.52             |
| 330 R               | R2, R3, R4, R6            | 4        | 0.14             | 0.56             |
| 10k                 | R11, R12, R13, R14, R1    | 8        | 0.027            | 0.216            |
| CG0603MLC-05E       | RV1, RV2                  | 2        | 0.15             | 0.3              |
| EVO-11L05R          | SW1                       | 1        | 0.07             | 0.07             |
| ATmega32U4RC-AU     | U1                        | 1        | 5.3              | 5.3              |
| TPS73633DBVR        | U2                        | 1        | 2.15             | 2.15             |
| LP5907MFX-2.85/NOPB | U3                        | 1        | 0.49             | 0.49             |
| PCAP04-AQFM-24      | U4                        | 1        | 7.66             | 7.66             |
| 61400416021         | USB1                      | 1        | 2.02             | 2.02             |
| ECS-8FMX-160-TR     | Y1                        | 1        | 4.15             | 4.15             |
|                     |                           |          | Total            | 31.415           |

Figure 57: Complete Bill of Materials for the Capacitive Torque Sensor

The complete Bill of Materials shown in Figure 57 contains all components required for the assembly of one sensor unit, categorized by:

- **Electronics Components:**

- Active components (MCU, regulators, ICs)
- Passive components (resistors, capacitors)
- Connectors and interfaces

- **Mechanical Parts:**

- Precision-machined components (shaft, disks)
- Enclosure and structural elements
- Fasteners and mounting hardware

- **PCB Details:**

- Board specifications (4-layer, 1.6mm thickness)
- Special materials (FR4, copper weight)

**Key Features of the BOM:**

- Each component includes manufacturer part numbers for precise sourcing
- Quantities are specified for single-unit production
- Critical components are highlighted with tolerance requirements
- Alternate part numbers are provided for key components

*Note: The BOM represents the final production version after all design iterations. Component availability and prices may vary based on market conditions.*

## 20 RTL Code for PCB (ATmega32U4)

### 20.1 Software Architecture

The firmware for the capacitive torque sensor consists of three main components:

- Capacitance measurement by CDC and send it to MCU via SPI
- MCU Calculation convert it into respective Torque value
- MCU send the Torque values via USB serial Commun

### 20.2 Code - Iteration 01

#### 20.2.1 main.c

Listing 1: Main C Code

```
1 #ifndef F_CPU
2 #define F_CPU 16000000UL // 16 MHz
3 #endif
4
5 #include <avr/io.h>
6 #include <util/delay.h>
7 #include <stdint.h>
8 #include <stdio.h>
9 #include <stdlib.h>
10 #include "Src/m_usb.h"
11 #include <math.h>
12
13 #define SS_PIN      PB0
14 #define MOSI_PIN    PB2
15 #define MISO_PIN    PB3
16 #define SCK_PIN     PB1
17
18 // Define polynomial coefficients for torque calculation
19 #define A3 0.0002
20 #define A2 -0.015
21 #define A1 3.2
22 #define A0 -150
23
24 // ===== SPI =====
25 void SPI_init(void) {
26     DDRB |= (1 << MOSI_PIN) | (1 << SCK_PIN) | (1 << SS_PIN); // Set MOSI,
27     // SCK, SS as output
28     DDRB &= ~(1 << MISO_PIN); // Set MISO as input
29     SPCR = (1 << SPE) | (1 << MSTR) | (1 << SPR0); // Enable SPI, Master,
30     // Fosc/16(SCK frequency)
31     SPSR = 0;
32 }
33
34 uint8_t SPI_transfer(uint8_t data) {
35     SPDR = data;
36     while (!(SPSR & (1 << SPIF)));
37     return SPDR;
38 }
```

```

37 // ===== PCAP04 SPI Interface =====
38 void PCAP04_select(void) {
39     PORTB &= ~(1 << PBO); // CS LOW
40 }
41
42 void PCAP04_deselect(void) {
43     PORTB |= (1 << PBO); // CS HIGH
44 }
45
46
47 void PCAP04_write(uint8_t addr, uint8_t data) {
48     PCAP04_select();
49     SPI_transfer(addr & 0x7F); // Write = MSB 0
50     SPI_transfer(data);
51     PCAP04_deselect();
52 }
53
54 uint8_t PCAP04_read(uint8_t addr) {
55     PCAP04_select();
56     SPI_transfer(addr | 0x80); // Read = MSB 1
57     uint8_t result = SPI_transfer(0x00);
58     PCAP04_deselect();
59     return result;
60 }
61
62 // ===== PCAP04 Config =====
63 void PCAP04_init(void) {
64     pcap_write_reg(0x00, 0x01); // Set Oscillator Frequency to 50 kHz
65     pcap_write_reg(0x04, 0b10010000); // CFG4: grounded sensor +
66     C_REF_INT
67     pcap_write_reg(0x06, 0x01); // CFG6: Enable PC0
68     pcap_write_reg(0x07, 0x08); // CFG7: averaging = 8
69     pcap_write_reg(0x08, 0x00); // CFG8: high byte of averaging
70     pcap_write_reg(0x09, 0x19); // CFG9 11 : CONV_TIME for 1 kHz
71     pcap_write_reg(0x0A, 0x00);
72     pcap_write_reg(0x0B, 0x00);
73     uint8_t reg17 = pcap_read_reg(0x11); // Read existing value
74     reg17 &= 0x03; // Clear bits 6:2 (keep bits 1:0)
75     reg17 |= (7 << 2); // Set C_REF_SEL = 7 (approx. 10
76     pF internal reference)
77     pcap_write_reg(0x11, reg17); // Write back updated value
78     pcap_write_reg(0x2F, 0x01); // CFG47: RUNBIT = 1
79 }
80
81 uint32_t PCAP04_read_result(void) {
82     uint32_t val = 0;
83     val |= ((uint32_t)PCAP04_read(0x03) << 24);
84     val |= ((uint32_t)PCAP04_read(0x02) << 16);
85     val |= ((uint32_t)PCAP04_read(0x01) << 8);
86     val |= ((uint32_t)PCAP04_read(0x00));
87     return val;
88 }

```

```

89 float PCAP04_to_pF(uint32_t raw, float Cref) {
90     float ratio = (float)raw / (1UL << 27); // 5.27 fixed-point
91     return ratio * Cref;
92 }
93
94 float calculateTorque(float x) {
95     return A3 * pow(x, 3) + A2 * pow(x, 2) + A1 * x + A0;
96 }
97
98 int main(void)
99 {
100     SPI_init();
101     m_usb_init();
102     _delay_ms(10);
103     PORTB |= (1 << PB0); // CS HIGH idle
104
105     PCAP04_init();
106     _delay_ms(100);
107
108     while (!m_usb_isconnected()) { }
109
110     while (1) {
111         uint32_t raw = PCAP04_read_result();
112         float cap_pf = PCAP04_to_pF(raw, 10.0f); // Assuming Cref = 10.0pF
113         float torque = calculateTorque(cap_pf);
114         m_usb_tx_long(torque);
115         m_usb_tx_push(); // Ensure transmission
116         _delay_ms(1); // 1 kHz loop // Prevent buffer overflow
117     }
118 }
```

## 20.3 Code - Iteration 02

### 20.3.1 main.c

Listing 2: USB header file

```

1 #define F_CPU 16000000UL
2 #include <avr/io.h>
3 #include <util/delay.h>
4 #include <stdio.h>
5 #include "m_usb.h"
6
7 // SPI Pin Definitions for ATmega32U4
8 #define SPI_DDR DDRB
9 #define SPI_PORT PORTB
10 #define MOSI PB2
11 #define MISO PB3
12 #define SCK PB1
13 #define SS PB0
14
15 // PCAP04 SPI Commands
16 #define OPCODE_WRITE_CFG 0xA3
17 #define OPCODE_READ_CFG 0x23
```

```

18 #define OPCODE_READ_RES      0x40
19 #define OPCODE_POR          0x88
20 #define OPCODE_INIT          0x8A
21 #define OPCODE_CDC_START     0x8C
22 #define OPCODE_TEST_READ     0x7E
23 #define WR_MEM               0xA0
24 #define RD_MEM               0x20
25
26 uint8_t standard_fw[548] = {
27     // Standard firmware data
28     // ... (truncated for brevity)
29 };
30
31 void SPI_Init(void) {
32     SPI_DDR |= (1 << MOSI) | (1 << SCK) | (1 << SS);
33     SPI_DDR &= ~(1 << MISO);
34     SPI_PORT |= (1 << SS);
35     SPCR = (1 << SPE) | (1 << MSTR) | (1 << CPHA) | (1 << SPR0);
36 }
37
38 uint8_t SPI_Transfer(uint8_t data) {
39     SPDR = data;
40     while (!(SPSR & (1 << SPIF)));
41     return SPDR;
42 }
43
44 void PCAP04_WriteRegister(uint8_t address, uint8_t data) {
45     SPI_PORT &= ~(1 << SS);
46     _delay_ms(1);
47     SPI_Transfer(OPCODE_WRITE_CFG);
48     SPI_Transfer(address | 0xC0);
49     SPI_Transfer(data);
50     _delay_ms(1);
51     SPI_PORT |= (1 << SS);
52     _delay_ms(1);
53 }
54
55 uint8_t PCAP04_ReadRegister(uint8_t address) {
56     uint8_t val;
57     SPI_PORT &= ~(1 << SS);
58     _delay_ms(1);
59     SPI_Transfer(OPCODE_READ_CFG);
60     SPI_Transfer(address | 0xC0);
61     val = SPI_Transfer(0x00);
62     _delay_ms(1);
63     SPI_PORT |= (1 << SS);
64     _delay_ms(1);
65     return val;
66 }
67
68 void Write_Byte_Auto_Incr(uint8_t opcode, uint8_t address, const uint8_t*
69     byte_array, int length) {
70     SPI_PORT &= ~(1 << SS);
71     _delay_ms(1);

```

```

71     SPI_Transfer(opcode);
72     SPI_Transfer(address);
73     for (int i = 0; i < length; i++) {
74         SPI_Transfer(byte_array[i]);
75         _delay_ms(5);
76     }
77     _delay_ms(10);
78     SPI_PORT |= (1 << SS);
79     _delay_ms(1);
80 }

81 void Read_BytE_Auto_Incr(uint8_t opcode, uint8_t address, int length) {
82     uint8_t val=0;
83     SPI_PORT &= ~(1 << SS);
84     _delay_ms(1);
85     SPI_Transfer(opcode);
86     SPI_Transfer(address);
87     for (int i = 0; i < length; i++) {
88         val=SPI_Transfer(0x00);
89         m_usb_tx_uint(val);
90         m_usb_tx_push();
91         _delay_ms(10);
92     }
93     SPI_PORT |= (1 << SS);
94     _delay_ms(1);
95 }
96

97 void PCAP04_CDC_START(void) {
98     SPI_PORT &= ~(1 << SS);
99     _delay_ms(1);
100    SPI_Transfer(OPCODE_CDC_START);
101    _delay_ms(1);
102    SPI_PORT |= (1 << SS);
103    _delay_ms(1);
104 }
105

106 void PCAP04_Init(void) {
107     SPI_PORT &= ~(1 << SS);
108     _delay_ms(1);
109     SPI_Transfer(OPCODE_INIT);
110     _delay_ms(1);
111     SPI_PORT |= (1 << SS);
112     _delay_ms(1);
113     PCAP04_WriteRegister(0x00, 0x01);
114     PCAP04_WriteRegister(0x04, 0b10010001);
115     PCAP04_WriteRegister(0x06, 0x3F);
116     PCAP04_WriteRegister(0x07, 0x08);
117     PCAP04_WriteRegister(0x08, 0x00);
118     PCAP04_WriteRegister(0x09, 0x19);
119     PCAP04_WriteRegister(0x0A, 0x00);
120     PCAP04_WriteRegister(0x0B, 0x00);
121     uint8_t reg17 = PCAP04_ReadRegister(0x11);
122     reg17 &= 0x03;
123     reg17 |= (7 << 2);
124 }
```

```

125     PCAP04_WriteRegister(0x11, reg17);
126 }
127
128 uint32_t PCAP04_ReadResult(uint8_t address) {
129     uint32_t val = 0;
130     SPI_PORT &= ~(1 << SS);
131     _delay_ms(1);
132     SPI_Transfer(OPCODE_READ_RES | address);
133     uint8_t byte1 = SPI_Transfer(0x00);
134     uint8_t byte2 = SPI_Transfer(0x00);
135     uint8_t byte3 = SPI_Transfer(0x00);
136     uint8_t byte4 = SPI_Transfer(0x00);
137     val = (byte1 << 24) | (byte2 << 16) | (byte3 << 8) | byte4;
138     _delay_ms(1);
139     SPI_PORT |= (1 << SS);
140     _delay_ms(1);
141     return val;
142 }
143
144 float binaryFractionToDecimal(uint8_t frac_bits, uint8_t num_bits) {
145     float result = 0.0;
146     for (uint8_t i = 0; i < num_bits; i++) {
147         if (frac_bits & (1 << (num_bits - 1 - i))) {
148             result += 1.0f / (1 << (i + 1));
149         }
150     }
151     return result;
152 }
153
154 int main(void) {
155     uint32_t result;
156     m_usb_init();
157     _delay_ms(1);
158     SPI_Init();
159     _delay_ms(1);
160     PCAP04_Init();
161     _delay_ms(1);
162
163     Write_Byte_Auto_Incr(WR_MEM, 0x00, standard_fw, 548);
164     _delay_ms(10);
165     Read_Byte_Auto_Incr(RD_MEM, 0X00, 10);
166     _delay_ms(10);
167     PCAP04_WriteRegister(0x2F, 0x01);
168     _delay_ms(10);
169     PCAP04_CDC_START();
170     _delay_ms(20);
171
172     while (1) {
173         result = PCAP04_ReadResult(0x00);
174         _delay_ms(10);
175
176         for (int i = 0; i < 200; i++) {
177             char buffer[16];
178             float r = (float)rand() / RAND_MAX;

```

```

179     float val = r/5;
180     dtostrf(val, 6, 3, buffer);
181     for (int i = 0; buffer[i] != '\0'; i++) {
182         m_usb_tx_char(buffer[i]);
183     }
184     m_usb_tx_char('\n');
185     m_usb_tx_push();
186     _delay_ms(100);
187 }
188
189     for (int i = 0; i < 200; i++) {
190         char buffer[16];
191         float r = (float)rand() / RAND_MAX;
192         float val = (0.2 + r);
193         if (val<= 1) {
194             dtostrf(val, 6, 3, buffer);
195             for (int i = 0; buffer[i] != '\0'; i++) {
196                 m_usb_tx_char(buffer[i]);
197             }
198             m_usb_tx_char('\n');
199             m_usb_tx_push();
200             _delay_ms(100);
201         }
202     }
203 }
204 }
```

### 20.3.2 usb.h & usb.c

Listing 3: USB Communication codes

```

1 #ifndef m_usb__
2 #define m_usb__
3
4 #include <avr/io.h>
5 #include <avr/interrupt.h>
6 #include <avr/pgmspace.h>
7 #include <stdlib.h>
8
9 void m_usb_init(void);
10 char m_usb_isconnected(void);
11 unsigned char m_usb_rx_available(void);
12 char m_usb_rx_char(void);
13 void m_usb_rx_flush(void);
14 char m_usb_tx_char(unsigned char c);
15 void m_usb_tx_hexchar(unsigned char i);
16 void m_usb_tx_hex(unsigned int i);
17 void m_usb_tx_int(int i);
18 void m_usb_tx_uint(unsigned int i);
19 void m_usb_tx_long(long i);
20 void m_usb_tx_ulong(unsigned long i);
21 #define m_usb_tx_string(s) print_P(PSTR(s))
22
23 // Back compatibility macros
```

```

24 #define usb_init()           m_usb_init()
25 #define usb_configured()     m_usb_isconnected()
26 #define usb_rx_available()   m_usb_rx_available()
27 #define usb_rx_flush()       m_usb_rx_flush()
28 #define usb_rx_char()        m_usb_rx_char()
29 #define usb_tx_char(val)     m_usb_tx_char(val)
30 #define usb_tx_hex(val)      m_usb_tx_hex(val)
31 #define usb_tx_decimal(val)  m_usb_tx_uint(val)
32 #define usb_tx_string(val)   m_usb_tx_string(val)
33 #define usb_tx_push()        m_usb_tx_push()

34
35 #endif
36
37 // -----
38
39 #define USB_SERIAL_PRIVATE_INCLUDE
40 #include "m_usb.h"
41 // ---- OVERLOADS FOR M1 BACK COMPATIBILITY ----
42 #define usb_init()           m_usb_init()
43 #define usb_configured()     m_usb_isconnected()

44 #define usb_rx_available()   m_usb_rx_available()
45 #define usb_rx_flush()       m_usb_rx_flush()
46 #define usb_rx_char()        m_usb_rx_char()

47 #define usb_tx_char(val)     m_usb_tx_char(val)
48 #define usb_tx_hex(val)      m_usb_tx_hex(val)
49 #define usb_tx_decimal(val)  m_usb_tx_uint(val)
50 #define usb_tx_string(val)   m_usb_tx_string(val)
51 #define usb_tx_push()        m_usb_tx_push()

52 #define m_usb_rx_ascii()     m_usb_rx_char()
53 #define m_usb_tx_ascii(val)  m_usb_tx_char(val)

54
55
56
57 // EVERYTHING ELSE
58 ****
59
60 // setup
61
62 int8_t usb_serial_putchar(uint8_t c);    // transmit a character
63 int8_t usb_serial_putchar_nowait(uint8_t c); // transmit a character, do
64                                         // not wait
65 int8_t usb_serial_write(const uint8_t *buffer, uint16_t size); // transmit
66                                         // a buffer
67 void print_P(const char *s);
68 void phex(unsigned char c);
69 void phex16(unsigned int i);
70 void m_usb_tx_hex8(unsigned char i);
71 void m_usb_tx_push(void);

72 // serial parameters

```

```

73 uint32_t usb_serial_get_baud(void); // get the baud rate
74 uint8_t usb_serial_get_stopbits(void); // get the number of stop bits
75 uint8_t usb_serial_get_paritytype(void); // get the parity type
76 uint8_t usb_serial_get_numbits(void); // get the number of data bits
77 uint8_t usb_serial_get_control(void); // get the RTS and DTR signal
    state
78 int8_t usb_serial_set_control(uint8_t signals); // set DSR, DCD, RI, etc
79
80 // constants corresponding to the various serial parameters
81 #define USB_SERIAL_DTR          0x01
82 #define USB_SERIAL_RTS          0x02
83 #define USB_SERIAL_1_STOP        0
84 #define USB_SERIAL_1_5_STOP      1
85 #define USB_SERIAL_2_STOP        2
86 #define USB_SERIAL_PARITY_NONE   0
87 #define USB_SERIAL_PARITY_ODD    1
88 #define USB_SERIAL_PARITY_EVEN   2
89 #define USB_SERIAL_PARITY_MARK   3
90 #define USB_SERIAL_PARITY_SPACE  4
91 #define USB_SERIAL_DCD          0x01
92 #define USB_SERIAL_DSR          0x02
93 #define USB_SERIAL_BREAK        0x04
94 #define USB_SERIAL_RI           0x08
95 #define USB_SERIAL_FRAME_ERR    0x10
96 #define USB_SERIAL_PARITY_ERR   0x20
97 #define USB_SERIAL_OVERRUN_ERR  0x40
98
99 // This file does not include the HID debug functions, so these empty
100 // macros replace them with nothing, so users can compile code that
101 // has calls to these functions.
102 #define usb_debug_putchar(c)
103 #define usb_debug_flush_output()
104
105 #define EP_TYPE_CONTROL          0x00
106 #define EP_TYPE_BULK_IN          0x81
107 #define EP_TYPE_BULK_OUT         0x80
108 #define EP_TYPE_INTERRUPT_IN     0xC1
109 #define EP_TYPE_INTERRUPT_OUT    0xC0
110 #define EP_TYPE_ISOCHRONOUS_IN   0x41
111 #define EP_TYPE_ISOCHRONOUS_OUT  0x40
112 #define EP_SINGLE_BUFFER         0x02
113 #define EP_DOUBLE_BUFFER         0x06
114 #define EP_SIZE(s) ((s) == 64 ? 0x30 : \
115 ((s) == 32 ? 0x20 : \
116 ((s) == 16 ? 0x10 : \
117 0x00)))
118
119 #define MAX_ENDPOINT            4
120
121 #define LSB(n) (n & 255)
122 #define MSB(n) ((n >> 8) & 255)
123
124 #define HW_CONFIG() (UHWCON = 0x01)
125

```

```

126 #ifdef M1
127 #define PLL_CONFIG() (PLLCSR = 0x02) // fixed to 8MHz clock
128 #else
129 #define PLL_CONFIG() (PLLCSR = 0x12) // 0001 0010 For a 16MHz clock
130 #endif
131
132 #define USB_CONFIG() (USBCON = ((1<<USBE)|(1<<OTGPADE)))
133 #define USB_FREEZE() (USBCON = ((1<<USBE)|(1<<FRZCLK)))
134
135 // standard control endpoint request types
136 #define GET_STATUS          0
137 #define CLEAR_FEATURE        1
138 #define SET_FEATURE          3
139 #define SET_ADDRESS          5
140 #define GET_DESCRIPTOR       6
141 #define GET_CONFIGURATION    8
142 #define SET_CONFIGURATION    9
143 #define GET_INTERFACE         10
144 #define SET_INTERFACE         11
145 // HID (human interface device)
146 #define HID_GET_REPORT       1
147 #define HID_GET_PROTOCOL     3
148 #define HID_SET_REPORT       9
149 #define HID_SET_IDLE         10
150 #define HID_SET_PROTOCOL     11
151 // CDC (communication class device)
152 #define CDC_SET_LINE_CODING  0x20
153 #define CDC_GET_LINE_CODING  0x21
154 #define CDC_SET_CONTROL_LINE_STATE 0x22
155
156
157 /*
***** */
158 *
159 * Configurable Options
160 *
161 *****/
162
163 #define STR_MANUFACTURER      L"J. Fiene"
164 #define STR_PRODUCT           L"M2"
165 #define STR_SERIAL_NUMBER     L"410"
166 #define VENDOR_ID              0x16C0 // must match INF file in Windows
167 #define PRODUCT_ID             0x047A // must match INF file in Windows
168 #define TRANSMIT_FLUSH_TIMEOUT 5 /* in milliseconds */
169 #define TRANSMIT_TIMEOUT        25 /* in milliseconds */
170 #define SUPPORT_ENDPOINT_HALT // can save 116 bytes by removing, makes
171     fully USB compliant
172 /*
***** */
173 *

```

```

174 * Endpoint Buffer Configuration
175 *
176 ****
177 */
178 #define ENDPOINT0_SIZE 16
179 #define CDC_ACM_ENDPOINT 2
180 #define CDC_RX_ENDPOINT 3
181 #define CDC_TX_ENDPOINT 4
182 #define CDC_ACM_SIZE 16
183 #define CDC_ACM_BUFFER EP_SINGLE_BUFFER
184 #define CDC_RX_SIZE 64
185 #define CDC_RX_BUFFER EP_DOUBLE_BUFFER
186 #define CDC_TX_SIZE 64
187 #define CDC_TX_BUFFER EP_DOUBLE_BUFFER
188
189 static const uint8_t PROGMEM endpoint_config_table[] = {
190     0,
191     1, EP_TYPE_INTERRUPT_IN, EP_SIZE(CDC_ACM_SIZE) | CDC_ACM_BUFFER,
192     1, EP_TYPE_BULK_OUT, EP_SIZE(CDC_RX_SIZE) | CDC_RX_BUFFER,
193     1, EP_TYPE_BULK_IN, EP_SIZE(CDC_TX_SIZE) | CDC_TX_BUFFER
194 };
195
196 /**
197 ****
198 *
199 * Descriptor Data
200 *
201 ****
202 */
203 static const uint8_t PROGMEM device_descriptor[] = {
204     18, // bLength
205     1, // bDescriptorType
206     0x00, 0x02, // bcdUSB
207     2, // bDeviceClass
208     0, // bDeviceSubClass
209     0, // bDeviceProtocol
210     ENDPOINT0_SIZE, // bMaxPacketSize0
211     LSB(VENDOR_ID), MSB(VENDOR_ID), // idVendor
212     LSB(PRODUCT_ID), MSB(PRODUCT_ID), // idProduct
213     0x00, 0x01, // bcdDevice
214     1, // iManufacturer
215     2, // iProduct
216     3, // iSerialNumber
217     1 // bNumConfigurations
218 };
219
220 #define CONFIG1_DESC_SIZE (9+9+5+5+4+5+7+9+7+7)
221 static const uint8_t PROGMEM config1_descriptor[CONFIG1_DESC_SIZE] = {
222     // configuration descriptor, USB spec 9.6.3, page 264-266, Table 9-10
223     9, // bLength;

```

```

224           2,                      // bDescriptorType;
225           LSB(CONFIG1_DESC_SIZE),      // wTotalLength
226           MSB(CONFIG1_DESC_SIZE),
227           2,                      // bNumInterfaces
228           1,                      // bConfigurationValue
229           0,                      // iConfiguration
230           0xCO,                   // bmAttributes
231           50,                     // bMaxPower
232           // interface descriptor, USB spec 9.6.5, page 267-269, Table 9-12
233           9,                      // bLength
234           4,                      // bDescriptorType
235           0,                      // bInterfaceNumber
236           0,                      // bAlternateSetting
237           1,                      // bNumEndpoints
238           0x02,                   // bInterfaceClass
239           0x02,                   // bInterfaceSubClass
240           0x01,                   // bInterfaceProtocol
241           0,                      // iInterface
242           // CDC Header Functional Descriptor, CDC Spec 5.2.3.1, Table 26
243           5,                      // bFunctionLength
244           0x24,                   // bDescriptorType
245           0x00,                   // bDescriptorSubtype
246           0x10, 0x01,             // bcdCDC
247           // Call Management Functional Descriptor, CDC Spec 5.2.3.2, Table 27
248           5,                      // bFunctionLength
249           0x24,                   // bDescriptorType
250           0x01,                   // bDescriptorSubtype
251           0x01,                   // bmCapabilities
252           1,                      // bDataInterface
253           // Abstract Control Management Functional Descriptor, CDC Spec
254           // 5.2.3.3, Table 28
255           4,                      // bFunctionLength
256           0x24,                   // bDescriptorType
257           0x02,                   // bDescriptorSubtype
258           0x06,                   // bmCapabilities
259           // Union Functional Descriptor, CDC Spec 5.2.3.8, Table 33
260           5,                      // bFunctionLength
261           0x24,                   // bDescriptorType
262           0x06,                   // bDescriptorSubtype
263           0,                      // bMasterInterface
264           1,                      // bSlaveInterface0
265           // endpoint descriptor, USB spec 9.6.6, page 269-271, Table 9-13
266           7,                      // bLength
267           5,                      // bDescriptorType
268           CDC_ACM_ENDPOINT | 0x80, // bEndpointAddress
269           0x03,                   // bmAttributes (0x03=intr)
270           CDC_ACM_SIZE, 0,        // wMaxPacketSize
271           64,                     // bInterval
272           // interface descriptor, USB spec 9.6.5, page 267-269, Table 9-12
273           9,                      // bLength
274           4,                      // bDescriptorType
275           1,                      // bInterfaceNumber
276           0,                      // bAlternateSetting
277           2,                      // bNumEndpoints

```

```

277     0x0A,           // bInterfaceClass
278     0x00,           // bInterfaceSubClass
279     0x00,           // bInterfaceProtocol
280     0,              // iInterface
281 // endpoint descriptor, USB spec 9.6.6, page 269-271, Table 9-13
282     7,              // bLength
283     5,              // bDescriptorType
284     CDC_RX_ENDPOINT, // bEndpointAddress
285     0x02,           // bmAttributes (0x02=bulk)
286     CDC_RX_SIZE, 0, // wMaxPacketSize
287     0,              // bInterval
288 // endpoint descriptor, USB spec 9.6.6, page 269-271, Table 9-13
289     7,              // bLength
290     5,              // bDescriptorType
291     CDC_TX_ENDPOINT | 0x80, // bEndpointAddress
292     0x02,           // bmAttributes (0x02=bulk)
293     CDC_TX_SIZE, 0, // wMaxPacketSize
294     0               // bInterval
295 };
296
297 // If you're desperate for a little extra code memory, these strings
298 // can be completely removed if iManufacturer, iProduct, iSerialNumber
299 // in the device descriptor are changed to zeros.
300 struct usb_string_descriptor_struct {
301     uint8_t bLength;
302     uint8_t bDescriptorType;
303     int16_t wString[];
304 };
305 static const struct usb_string_descriptor_struct PROGMEM string0 = {
306     4,
307     3,
308     {0x0409}
309 };
310 static const struct usb_string_descriptor_struct PROGMEM string1 = {
311     sizeof(STR_MANUFACTURER),
312     3,
313     STR_MANUFACTURER
314 };
315 static const struct usb_string_descriptor_struct PROGMEM string2 = {
316     sizeof(STR_PRODUCT),
317     3,
318     STR_PRODUCT
319 };
320 static const struct usb_string_descriptor_struct PROGMEM string3 = {
321     sizeof(STR_SERIAL_NUMBER),
322     3,
323     STR_SERIAL_NUMBER
324 };
325
326 // This table defines which descriptor data is sent for each specific
327 // request from the host (in wValue and wIndex).
328 static const struct descriptor_list_struct {
329     uint16_t    wValue;
330     uint16_t    wIndex;

```

```

331     const uint8_t    *addr;
332     uint8_t        length;
333 } PROGMEM descriptor_list[] = {
334     {0x0100, 0x0000, device_descriptor, sizeof(device_descriptor)},
335     {0x0200, 0x0000, config1_descriptor, sizeof(config1_descriptor)},
336     {0x0300, 0x0000, (const uint8_t *)&string0, 4},
337     {0x0301, 0x0409, (const uint8_t *)&string1, sizeof(STR_MANUFACTURER)},
338     {0x0302, 0x0409, (const uint8_t *)&string2, sizeof(STR_PRODUCT)},
339     {0x0303, 0x0409, (const uint8_t *)&string3, sizeof(STR_SERIAL_NUMBER)}
340 };
341 #define NUM_DESC_LIST (sizeof(descriptor_list)/sizeof(struct
342             descriptor_list_struct))
343
344 /*
345 *
346 *   Variables - these are the only non-stack RAM usage
347 *
348 ****
349 */
350 // zero when we are not configured, non-zero when enumerated
351 static volatile uint8_t usb_configuration=0;
352
353 // the time remaining before we transmit any partially full
354 // packet, or send a zero length packet.
355 static volatile uint8_t transmit_flush_timer=0;
356 static uint8_t transmit_previous_timeout=0;
357
358 // serial port settings (baud rate, control signals, etc) set
359 // by the PC. These are ignored, but kept in RAM.
360 static uint8_t cdc_line_coding[7]={0x00, 0xE1, 0x00, 0x00, 0x00, 0x00, 0
361     x08};
362 static uint8_t cdc_line_rtsdtr=0;
363
364 /*
365 *
366 *   Public Functions - these are the API intended for the user
367 *
368 ****
369 */
370 // initialize USB serial
371 void m_usb_init(void)
372 {
373     HW_CONFIG();
374     USB_FREEZE();           // enable USB
375     PLL_CONFIG();          // config PLL, 16 MHz xtal
376     while (!(PLLCSR & (1<<PLOCK))) ;    // wait for PLL lock

```

```

377     USB_CONFIG();           // start USB clock
378     UDCON = 0;             // enable attach resistor
379     usb_configuration = 0;
380     cdc_line_rtsdtr = 0;
381     UDIEN = (1<<EORSTE)|(1<<SOFE);
382     sei();
383 }
384
385 // return 0 if the USB is not configured, or the configuration
386 // number selected by the HOST
387 char m_usb_isconnected(void)
388 {
389     return (char)usb_configuration;
390 }
391
392 // get the next character, or -1 if nothing received
393 char m_usb_rx_char(void)
394 {
395     uint8_t c, intr_state;
396
397     // interrupts are disabled so these functions can be
398     // used from the main program or interrupt context,
399     // even both in the same program!
400     intr_state = SREG;
401     cli();
402     if (!usb_configuration) {
403         SREG = intr_state;
404         return -1;
405     }
406     UENUM = CDC_RX_ENDPOINT;
407     if (!(UEINTX & (1<<RWAL))) {
408         // no data in buffer
409         SREG = intr_state;
410         return -1;
411     }
412     // take one byte out of the buffer
413     c = UEDATX;
414     // if buffer completely used, release it
415     if (!(UEINTX & (1<<RWAL))) UEINTX = 0x6B;
416     SREG = intr_state;
417     return (char)c;
418 }
419
420 // number of bytes available in the receive buffer
421 unsigned char m_usb_rx_available(void)
422 {
423     uint8_t n=0, intr_state;
424
425     intr_state = SREG;
426     cli();
427     if (usb_configuration) {
428         UENUM = CDC_RX_ENDPOINT;
429         n = UEBCLX;
430     }

```

```

431     SREG = intr_state;
432     return (unsigned char)n;
433 }
434
435 // discard any buffered input
436 void m_usb_rx_flush(void)
437 {
438     uint8_t intr_state;
439
440     if (usb_configuration) {
441         intr_state = SREG;
442         cli();
443         UENUM = CDC_RX_ENDPOINT;
444         while ((UEINTX & (1<<RWAL))) {
445             UEINTX = 0x6B;
446         }
447         SREG = intr_state;
448     }
449 }
450
451 // transmit a character.  0 returned on success, -1 on error
452 char m_usb_tx_char(unsigned char c)
453 {
454     uint8_t timeout, intr_state;
455
456     // if we're not online (enumerated and configured), error
457     if (!usb_configuration) return -1;
458     // interrupts are disabled so these functions can be
459     // used from the main program or interrupt context,
460     // even both in the same program!
461     intr_state = SREG;
462     cli();
463     UENUM = CDC_TX_ENDPOINT;
464     // if we gave up due to timeout before, don't wait again
465     if (transmit_previous_timeout) {
466         if (!(UEINTX & (1<<RWAL))) {
467             SREG = intr_state;
468             return -1;
469         }
470         transmit_previous_timeout = 0;
471     }
472     // wait for the FIFO to be ready to accept data
473     timeout = UDFNUML + TRANSMIT_TIMEOUT;
474     while (1) {
475         // are we ready to transmit?
476         if (UEINTX & (1<<RWAL)) break;
477         SREG = intr_state;
478         // have we waited too long? This happens if the user
479         // is not running an application that is listening
480         if (UDFNUML == timeout) {
481             transmit_previous_timeout = 1;
482             return -1;
483         }
484         // has the USB gone offline?

```

```

485     if (!usb_configuration) return -1;
486     // get ready to try checking again
487     intr_state = SREG;
488     cli();
489     UENUM = CDC_TX_ENDPOINT;
490 }
491 // actually write the byte into the FIFO
492 UEDATX = (uint8_t)c;
493 // if this completed a packet, transmit it now!
494 if (!(UEINTX & (1<<RWAL))) UEINTX = 0x3A;
495 transmit_flush_timer = TRANSMIT_FLUSH_TIMEOUT;
496 SREG = intr_state;
497 return 0;
498 }

499
500
501 // transmit a character, but do not wait if the buffer is full,
502 // 0 returned on success, -1 on buffer full or error
503 int8_t usb_serial_putchar_nowait(uint8_t c)
504 {
505     uint8_t intr_state;
506
507     if (!usb_configuration) return -1;
508     intr_state = SREG;
509     cli();
510     UENUM = CDC_TX_ENDPOINT;
511     if (!(UEINTX & (1<<RWAL))) {
512         // buffer is full
513         SREG = intr_state;
514         return -1;
515     }
516     // actually write the byte into the FIFO
517     UEDATX = c;
518     // if this completed a packet, transmit it now!
519     if (!(UEINTX & (1<<RWAL))) UEINTX = 0x3A;
520     transmit_flush_timer = TRANSMIT_FLUSH_TIMEOUT;
521     SREG = intr_state;
522     return 0;
523 }

524
525 // transmit a buffer.
526 // 0 returned on success, -1 on error
527 // This function is optimized for speed! Each call takes approx 6.1 us
528 // overhead
529 // plus 0.25 us per byte. 12 Mbit/sec USB has 8.67 us per-packet overhead
530 // and
531 // takes 0.67 us per byte. If called with 64 byte packet-size blocks,
532 // this function
533 // can transmit at full USB speed using 43% CPU time. The maximum
534 // theoretical speed
535 // is 19 packets per USB frame, or 1216 kbytes/sec. However, bulk
536 // endpoints have the
537 // lowest priority, so any other USB devices will likely reduce the speed.
538 // Speed

```

```

533 // can also be limited by how quickly the PC-based software reads data, as
534 // the host
535 // controller in the PC will not allocate bandwidth without a pending read
536 // request.
537 // (thanks to Victor Suarez for testing and feedback and initial code)
538
539 int8_t usb_serial_write(const uint8_t *buffer, uint16_t size)
540 {
541     uint8_t timeout, intr_state, write_size;
542
543     // if we're not online (enumerated and configured), error
544     if (!usb_configuration) return -1;
545     // interrupts are disabled so these functions can be
546     // used from the main program or interrupt context,
547     // even both in the same program!
548     intr_state = SREG;
549     cli();
550     UENUM = CDC_TX_ENDPOINT;
551     // if we gave up due to timeout before, don't wait again
552     if (transmit_previous_timeout) {
553         if (!(UEINTX & (1<<RWAL))) {
554             SREG = intr_state;
555             return -1;
556         }
557         transmit_previous_timeout = 0;
558     }
559     // each iteration of this loop transmits a packet
560     while (size) {
561         // wait for the FIFO to be ready to accept data
562         timeout = UDFNUML + TRANSMIT_TIMEOUT;
563         while (1) {
564             // are we ready to transmit?
565             if (UEINTX & (1<<RWAL)) break;
566             SREG = intr_state;
567             // have we waited too long? This happens if the user
568             // is not running an application that is listening
569             if (UDFNUML == timeout) {
570                 transmit_previous_timeout = 1;
571                 return -1;
572             }
573             // has the USB gone offline?
574             if (!usb_configuration) return -1;
575             // get ready to try checking again
576             intr_state = SREG;
577             cli();
578             UENUM = CDC_TX_ENDPOINT;
579         }
580         // compute how many bytes will fit into the next packet
581         write_size = CDC_TX_SIZE - UEBCLX;
582         if (write_size > size) write_size = size;
583         size -= write_size;
584
585         // write the packet

```

```

585     switch (write_size) {
586         #if (CDC_TX_SIZE == 64)
587             case 64: UEDATX = *buffer++;
588             case 63: UEDATX = *buffer++;
589             case 62: UEDATX = *buffer++;
590             case 61: UEDATX = *buffer++;
591             case 60: UEDATX = *buffer++;
592             case 59: UEDATX = *buffer++;
593             case 58: UEDATX = *buffer++;
594             case 57: UEDATX = *buffer++;
595             case 56: UEDATX = *buffer++;
596             case 55: UEDATX = *buffer++;
597             case 54: UEDATX = *buffer++;
598             case 53: UEDATX = *buffer++;
599             case 52: UEDATX = *buffer++;
600             case 51: UEDATX = *buffer++;
601             case 50: UEDATX = *buffer++;
602             case 49: UEDATX = *buffer++;
603             case 48: UEDATX = *buffer++;
604             case 47: UEDATX = *buffer++;
605             case 46: UEDATX = *buffer++;
606             case 45: UEDATX = *buffer++;
607             case 44: UEDATX = *buffer++;
608             case 43: UEDATX = *buffer++;
609             case 42: UEDATX = *buffer++;
610             case 41: UEDATX = *buffer++;
611             case 40: UEDATX = *buffer++;
612             case 39: UEDATX = *buffer++;
613             case 38: UEDATX = *buffer++;
614             case 37: UEDATX = *buffer++;
615             case 36: UEDATX = *buffer++;
616             case 35: UEDATX = *buffer++;
617             case 34: UEDATX = *buffer++;
618             case 33: UEDATX = *buffer++;
619         #endif
620         #if (CDC_TX_SIZE >= 32)
621             case 32: UEDATX = *buffer++;
622             case 31: UEDATX = *buffer++;
623             case 30: UEDATX = *buffer++;
624             case 29: UEDATX = *buffer++;
625             case 28: UEDATX = *buffer++;
626             case 27: UEDATX = *buffer++;
627             case 26: UEDATX = *buffer++;
628             case 25: UEDATX = *buffer++;
629             case 24: UEDATX = *buffer++;
630             case 23: UEDATX = *buffer++;
631             case 22: UEDATX = *buffer++;
632             case 21: UEDATX = *buffer++;
633             case 20: UEDATX = *buffer++;
634             case 19: UEDATX = *buffer++;
635             case 18: UEDATX = *buffer++;
636             case 17: UEDATX = *buffer++;
637         #endif
638         #if (CDC_TX_SIZE >= 16)

```

```

639         case 16: UEDATX = *buffer++;
640         case 15: UEDATX = *buffer++;
641         case 14: UEDATX = *buffer++;
642         case 13: UEDATX = *buffer++;
643         case 12: UEDATX = *buffer++;
644         case 11: UEDATX = *buffer++;
645         case 10: UEDATX = *buffer++;
646         case 9: UEDATX = *buffer++;
647     #endif
648         case 8: UEDATX = *buffer++;
649         case 7: UEDATX = *buffer++;
650         case 6: UEDATX = *buffer++;
651         case 5: UEDATX = *buffer++;
652         case 4: UEDATX = *buffer++;
653         case 3: UEDATX = *buffer++;
654         case 2: UEDATX = *buffer++;
655     default:
656         case 1: UEDATX = *buffer++;
657         case 0: break;
658     }
659 // if this completed a packet, transmit it now!
660 if (!(UEINTX & (1<<RWAL))) UEINTX = 0x3A;
661 transmit_flush_timer = TRANSMIT_FLUSH_TIMEOUT;
662 }
663 SREG = intr_state;
664 return 0;
665 }

666

667
// immediately transmit any buffered output.
// This doesn't actually transmit the data - that is impossible!
// USB devices only transmit when the host allows, so the best
// we can do is release the FIFO buffer for when the host wants it
672 void m_usb_tx_push(void)
{
673     uint8_t intr_state;

674     intr_state = SREG;
675
676     cli();
677     if (transmit_flush_timer) {
678         UENUM = CDC_TX_ENDPOINT;
679         UEINTX = 0x3A;
680         transmit_flush_timer = 0;
681     }
682     SREG = intr_state;
683 }

684

685
// functions to read the various async serial settings. These
686 // aren't actually used by USB at all (communication is always
687 // at full USB speed), but they are set by the host so we can
688 // set them properly if we're converting the USB to a real serial
689 // communication
690
691 //uint32_t usb_serial_get_baud(void)

```

```

693 //{
694 //    return *(uint32_t *)cdc_line_coding;
695 //}
696 uint8_t usb_serial_get_stopbits(void)
697 {
698     return cdc_line_coding[4];
699 }
700 uint8_t usb_serial_get_paritytype(void)
701 {
702     return cdc_line_coding[5];
703 }
704 uint8_t usb_serial_get_numbits(void)
705 {
706     return cdc_line_coding[6];
707 }
708 uint8_t usb_serial_get_control(void)
709 {
710     return cdc_line_rtsdtr;
711 }
712 // write the control signals, DCD, DSR, RI, etc
713 // There is no CTS signal. If software on the host has transmitted
714 // data to you but you haven't been calling the getchar function,
715 // it remains buffered (either here or on the host) and can not be
716 // lost because you weren't listening at the right time, like it
717 // would in real serial communication.
718 // TODO: this function is untested. Does it work? Please email
719 // paul@pjrc.com if you have tried it....
720 int8_t usb_serial_set_control(uint8_t signals)
721 {
722     uint8_t intr_state;
723
724     intr_state = SREG;
725     cli();
726     if (!usb_configuration) {
727         // we're not enumerated/configured
728         SREG = intr_state;
729         return -1;
730     }
731
732     UENUM = CDC_ACM_ENDPOINT;
733     if (!(UEINTX & (1<<RWAL))) {
734         // unable to write
735         // TODO; should this try to abort the previously
736         // buffered message??
737         SREG = intr_state;
738         return -1;
739     }
740     UEDATX = 0xA1;
741     UEDATX = 0x20;
742     UEDATX = 0;
743     UEDATX = 0;
744     UEDATX = 0; // TODO: should this be 1 or 0 ???
745     UEDATX = 0;
746     UEDATX = 2;

```

```

747     UEDATX = 0;
748     UEDATX = signals;
749     UEDATX = 0;
750     UEINTX = 0x3A;
751     SREG = intr_state;
752     return 0;
753 }
754
755
756
757 /*
758 *
759 *   Private Functions - not intended for general user consumption....
760 *
761 ****
762 */
763
764 // USB Device Interrupt - handle all device-level events
765 // the transmit buffer flushing is triggered by the start of frame
766 //
767 ISR(USB_GEN_vect)
768 {
769     uint8_t intbits, t;
770
771     intbits = UDINT;
772     UDINT = 0;
773     if (intbits & (1<<EORSTI)) {
774         UENUM = 0;
775         UECONX = 1;
776         UECFGOX = EP_TYPE_CONTROL;
777         UECFG1X = EP_SIZE(ENDPOINT0_SIZE) | EP_SINGLE_BUFFER;
778         UEIENX = (1<<RXSTPE);
779         usb_configuration = 0;
780         cdc_line_rtsdtr = 0;
781     }
782     if (intbits & (1<<SOFI)) {
783         if (usb_configuration) {
784             t = transmit_flush_timer;
785             if (t) {
786                 transmit_flush_timer = --t;
787                 if (!t) {
788                     UENUM = CDC_TX_ENDPOINT;
789                     UEINTX = 0x3A;
790                 }
791             }
792         }
793     }
794 }
795
796
797 // Misc functions to wait for ready and send/receive packets

```

```

798 static inline void usb_wait_in_ready(void)
799 {
800     while (!(UEINTX & (1<<TXINI))) ;
801 }
802 static inline void usb_send_in(void)
803 {
804     UEINTX = ~(1<<TXINI);
805 }
806 static inline void usb_wait_receive_out(void)
807 {
808     while !(UEINTX & (1<<RXOUTI))) ;
809 }
810 static inline void usb_ack_out(void)
811 {
812     UEINTX = ~(1<<RXOUTI);
813 }
814
815
816
817 // USB Endpoint Interrupt - endpoint 0 is handled here. The
818 // other endpoints are manipulated by the user-callable
819 // functions, and the start-of-frame interrupt.
820 //
821 ISR(USB_COM_vect)
822 {
823     uint8_t intbits;
824     const uint8_t *list;
825     const uint8_t *cfg;
826     uint8_t i, n, len, en;
827     uint8_t *p;
828     uint8_t bmRequestType;
829     uint8_t bRequest;
830     uint16_t wValue;
831     uint16_t wIndex;
832     uint16_t wLength;
833     uint16_t desc_val;
834     const uint8_t *desc_addr;
835     uint8_t desc_length;
836
837     UENUM = 0;
838     intbits = UEINTX;
839     if (intbits & (1<<RXSTPI)) {
840         bmRequestType = UEDATX;
841         bRequest = UEDATX;
842         wValue = UEDATX;
843         wValue |= (UEDATX << 8);
844         wIndex = UEDATX;
845         wIndex |= (UEDATX << 8);
846         wLength = UEDATX;
847         wLength |= (UEDATX << 8);
848         UEINTX = ~((1<<RXSTPI) | (1<<RXOUTI) | (1<<TXINI));
849         if (bRequest == GET_DESCRIPTOR) {
850             list = (const uint8_t *)descriptor_list;
851             for (i=0; ; i++) {

```

```

852         if (i >= NUM_DESC_LIST) {
853             UECONX = (1<<STALLRQ)|(1<<EPEN); //stall
854             return;
855         }
856         desc_val = pgm_read_word(list);
857         if (desc_val != wValue) {
858             list += sizeof(struct descriptor_list_struct);
859             continue;
860         }
861         list += 2;
862         desc_val = pgm_read_word(list);
863         if (desc_val != wIndex) {
864             list += sizeof(struct descriptor_list_struct)-2;
865             continue;
866         }
867         list += 2;
868         desc_addr = (const uint8_t *)pgm_read_word(list);
869         list += 2;
870         desc_length = pgm_read_byte(list);
871         break;
872     }
873     len = (wLength < 256) ? wLength : 255;
874     if (len > desc_length) len = desc_length;
875     do {
876         // wait for host ready for IN packet
877         do {
878             i = UEINTX;
879         } while (!(i & ((1<<TXINI)|(1<<RXOUTI))));
880         if (i & (1<<RXOUTI)) return; // abort
881         // send IN packet
882         n = len < ENDPOINT0_SIZE ? len : ENDPOINT0_SIZE;
883         for (i = n; i-- ) {
884             UEDATX = pgm_read_byte(desc_addr++);
885         }
886         len -= n;
887         usb_send_in();
888     } while (len || n == ENDPOINT0_SIZE);
889     return;
890 }
891 if (bRequest == SET_ADDRESS) {
892     usb_send_in();
893     usb_wait_in_ready();
894     UDADDR = wValue | (1<<ADDEN);
895     return;
896 }
897 if (bRequest == SET_CONFIGURATION && bmRequestType == 0) {
898     usb_configuration = wValue;
899     cdc_line_rtsdtr = 0;
900     transmit_flush_timer = 0;
901     usb_send_in();
902     cfg = endpoint_config_table;
903     for (i=1; i<5; i++) {
904         UENUM = i;
905         en = pgm_read_byte(cfg++);

```

```

906         UECONX = en;
907         if (en) {
908             UECFG0X = pgm_read_byte(cfg++);
909             UECFG1X = pgm_read_byte(cfg++);
910         }
911     }
912     UERST = 0x1E;
913     UERST = 0;
914     return;
915 }
916 if (bRequest == GET_CONFIGURATION && bmRequestType == 0x80) {
917     usb_wait_in_ready();
918     UEDATX = usb_configuration;
919     usb_send_in();
920     return;
921 }
922 if (bRequest == CDC_GET_LINE_CODING && bmRequestType == 0xA1) {
923     usb_wait_in_ready();
924     p = cdc_line_coding;
925     for (i=0; i<7; i++) {
926         UEDATX = *p++;
927     }
928     usb_send_in();
929     return;
930 }
931 if (bRequest == CDC_SET_LINE_CODING && bmRequestType == 0x21) {
932     usb_wait_receive_out();
933     p = cdc_line_coding;
934     for (i=0; i<7; i++) {
935         *p++ = UEDATX;
936     }
937     usb_ack_out();
938     usb_send_in();
939     return;
940 }
941 if (bRequest == CDC_SET_CONTROL_LINE_STATE && bmRequestType == 0x21) {
942     cdc_line_rtsdtr = wValue;
943     usb_wait_in_ready();
944     usb_send_in();
945     return;
946 }
947 if (bRequest == GET_STATUS) {
948     usb_wait_in_ready();
949     i = 0;
950     #ifdef SUPPORT_ENDPOINT_HALT
951     if (bmRequestType == 0x82) {
952         UENUM = wIndex;
953         if (UECONX & (1<<STALLRQ)) i = 1;
954         UENUM = 0;
955     }
956     #endif
957     UEDATX = i;
958     UEDATX = 0;

```

```

959         usb_send_in();
960         return;
961     }
962     #ifdef SUPPORT_ENDPOINT_HALT
963     if ((bRequest == CLEAR_FEATURE || bRequest == SET_FEATURE)
964         && bmRequestType == 0x02 && wValue == 0) {
965         i = wIndex & 0x7F;
966         if (i >= 1 && i <= MAX_ENDPOINT) {
967             usb_send_in();
968             UENUM = i;
969             if (bRequest == SET_FEATURE) {
970                 UECONX = (1<<STALLRQ)|(1<<EPEN);
971             } else {
972                 UECONX = (1<<STALLRQC)|(1<<RSTDT)|(1<<EPEN);
973                 UERST = (1 << i);
974                 UERST = 0;
975             }
976             return;
977         }
978     }
979     #endif
980 }
981 UECONX = (1<<STALLRQ) | (1<<EPEN); // stall
982 }

983
984
985 // BELOW FROM PRINT.C
986
987 void print_P(const char *s)
988 {
989     char c;
990
991     while (1) {
992         c = pgm_read_byte(s++);
993         if (!c) break;
994         if (c == '\n') usb_tx_char('\r');
995         usb_tx_char(c);
996     }
997 }
998
999 void phex1(unsigned char c)
1000 {
1001     usb_tx_char(c + ((c < 10) ? '0' : 'A' - 10));
1002 }
1003
1004 void phex(unsigned char c)
1005 {
1006     phex1(c >> 4);
1007     phex1(c & 15);
1008 }
1009
1010 void m_usb_tx_hex(unsigned int i)
1011 {
1012     phex(i >> 8);

```

```

1013     phex(i);
1014 }
1015
1016 void m_usb_tx_hexchar(unsigned char i)
1017 {
1018     phex(i);
1019 }
1020
1021 void m_usb_tx_int(int i)
1022 {
1023     char string[7] = {0,0,0,0,0,0,0};
1024     itoa(i,string,10);
1025     for(i=0;i<7;i++){
1026         if(string[i]){
1027             m_usb_tx_char(string[i]);
1028         }
1029     }
1030 }
1031
1032 void m_usb_tx_uint(unsigned int i)
1033 {
1034     char string[6] = {0,0,0,0,0,0};
1035     utoa(i,string,10);
1036     for(i=0;i<5;i++){
1037         if(string[i]){
1038             m_usb_tx_char(string[i]);
1039         }
1040     }
1041 }
1042
1043 void m_usb_tx_long(long i)
1044 {
1045     char string[11] = {0,0,0,0,0,0,0,0,0,0,0};
1046     ltoa(i,string,10);
1047     for(i=0;i<11;i++){
1048         if(string[i]){
1049             m_usb_tx_char(string[i]);
1050         }
1051     }
1052 }
1053
1054 void m_usb_tx_ulong(unsigned long i)
1055 {
1056     char string[11] = {0,0,0,0,0,0,0,0,0,0,0};
1057     ultoa(i,string,10);
1058     for(i=0;i<10;i++){
1059         if(string[i]){
1060             m_usb_tx_char(string[i]);
1061         }
1062     }
1063 }

```

## 21 PC Interface Software for Torque Visualization

To provide real-time monitoring and analysis of the torque values measured by our capacitive torque sensor, we developed a custom PC application named **CAPTORQ**. This application enables serial communication with the sensor via a USB interface and visually plots the incoming torque data over time.

### Features

The main features of the CAPTORQ software include:

- Real-time plotting of torque values against time.
- Adjustable serial port and baud rate selection for flexible connectivity.
- Data snapshot and analysis functions for post-processing.
- Ability to pause, clear, and save data during a measurement session.

The plotting area displays the torque value (Y-axis) as a function of time (X-axis), allowing users to track dynamic changes in torque. The application is built using Python and the PyQt5 library for GUI design, with matplotlib used for plotting the live data stream.

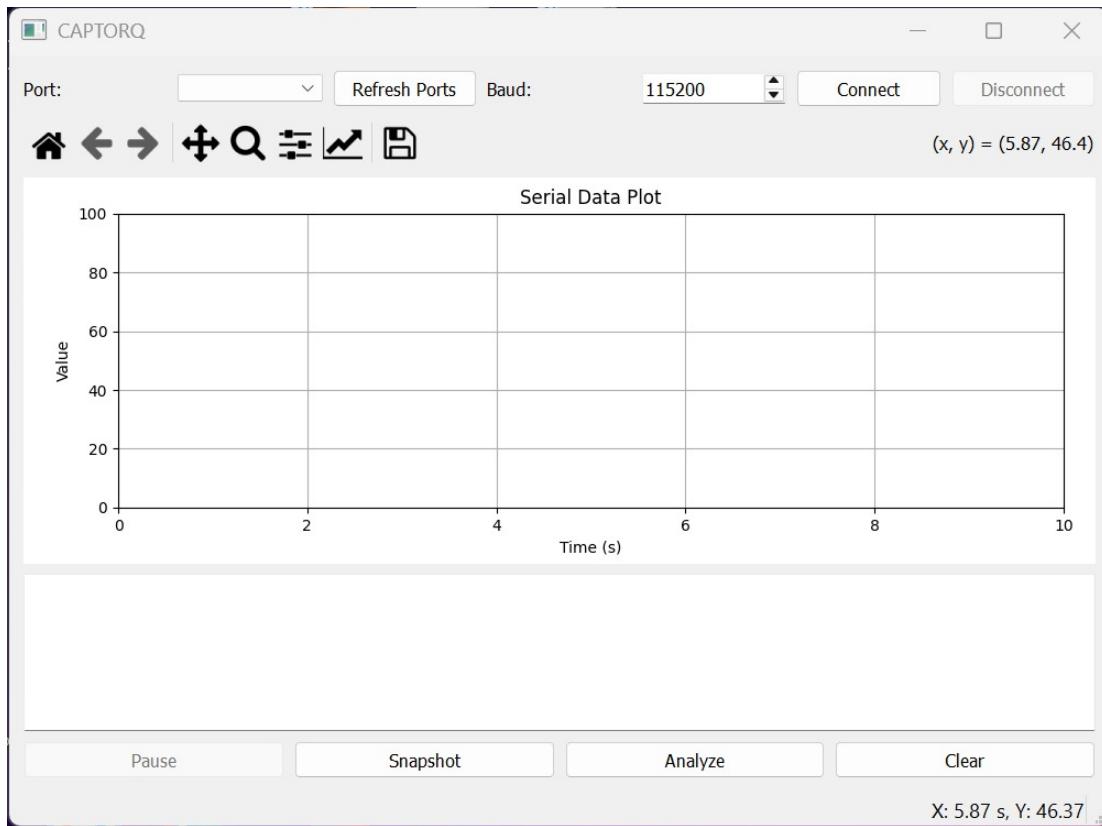


Figure 58: CAPTORQ Software Interface for Visualizing Torque Sensor Output

This tool significantly enhances usability and data interpretability for both debugging and experimental purposes, making the system more practical for laboratory and potential industrial use.

## 22 Production Cost Analysis for One Product

The estimated cost breakdown for manufacturing one capacitive torque sensor unit is presented in Table 3. All costs are calculated in Sri Lankan Rupees (LKR).

Table 3: Unit Production Cost Breakdown

| Component/Process                  | Unit Cost (LKR) | Percentage  |
|------------------------------------|-----------------|-------------|
| PCB Manufacturing + Shipping       | 2,470           | 9.7%        |
| Electronic Components for PCB      | 9,300           | 36.5%       |
| Enclosures, Metal Sheets and Shaft | 4,200           | 16.5%       |
| Cutting Disk and Holders           | 6,500           | 25.5%       |
| Assembly and Physical things       | 3,000           | 11.8%       |
| <b>Total Production Cost</b>       | <b>25,470</b>   | <b>100%</b> |

Since we spent around **Rs. 25,000** to make one product when we try to manufacture this in a large scale we will have less spending.

### 22.1 Cost Breakdown Details

- **PCB Costs:** Includes 4-layer board fabrication, solder mask, silkscreen, and international shipping charges from the manufacturer.
- **Electronic Components:** Covers all SMD and through-hole components including the Atmega32U4 microcontroller, voltage regulators, connectors, and passive components.
- **Mechanical Parts:**
  - Enclosure CNC machining and finishing
  - Precision shaft turning and heat treatment
  - Surface treatment for corrosion resistance
- **Disk Fabrication:**
  - Laser cutting of capacitive plates
  - Precision drilling for mounting holes
  - Surface polishing for consistent capacitance
- **Assembly Costs:**
  - PCB population and soldering
  - Mechanical assembly and alignment
  - Quality control and testing

## 23 Amendments Made Since First Evaluation

\* Amending the Figure 13. (CDC Calculation)

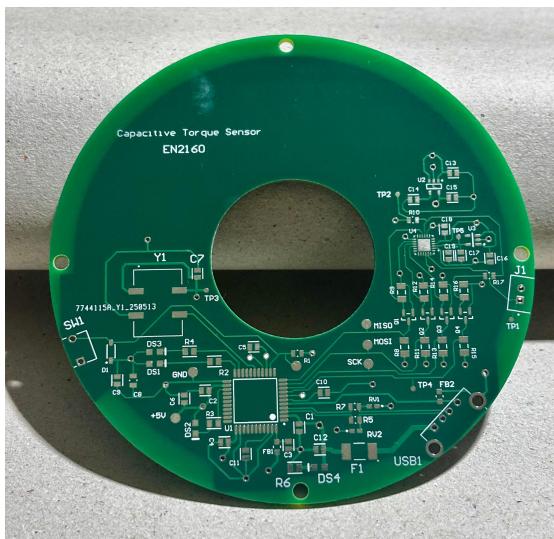
The image shows handwritten calculations for a CDC (Clock-Domain Crossing) full calculation. At the top, it says "FCD 2212". Below that, it calculates conversion time as  $\frac{15}{1000} = 1 \text{ ms}$ . Then, it defines  $t_{\text{ext}} = C_{\text{Hx}} \cdot R_{\text{Count}} \times 16 + 14$ . It then equates  $1 \times 10^{-3} = \frac{C_{\text{Hx}} \cdot R_{\text{Count}} \times 16 + 14}{40 \text{ MHz}}$  and solves for  $R_{\text{Count}} \approx \frac{40 \times 10^6 \times 10^{-3}}{16} = 2500$ . Next, it states "0.3 & F at 100 SPS noise is given." and converts  $100 \text{ SPS} \rightarrow t_{\text{ext}} = 10 \text{ ms}$ . It then calculates  $R_{\text{Count}} = \frac{40 \times 10^6 \times 10^{-3}}{16} = 25000$ . Following this, it discusses noise with the formula  $\text{Noise} \propto \frac{1}{\sqrt{R_{\text{Count}}}}$ , noting "oversampling theory (ADC)". It defines  $n_1 \propto \frac{1}{\sqrt{25000}}$  and  $n_2 \propto \frac{1}{\sqrt{2500}}$ , resulting in  $n_2 = n_1 \sqrt{10} = 0.95 \text{ ff} \approx 950 \text{ aF}$ . Finally, it notes "For PCAP04" and "156 aF noise at 1kHz".

Figure 59: CDC FULL Calculation

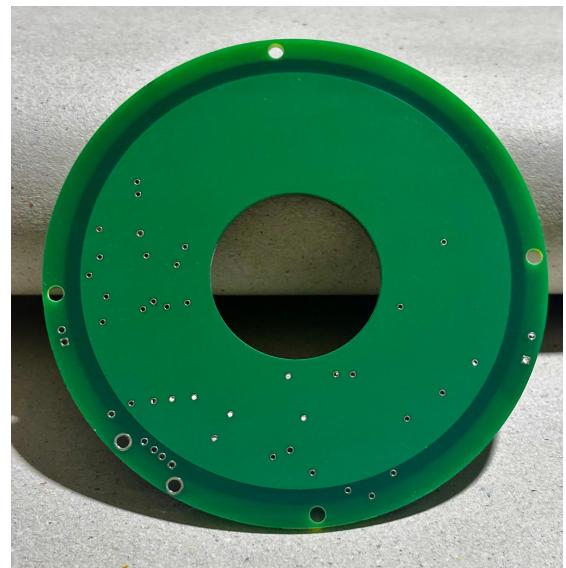
### 23.1 PCB Soldering and Testing

The printed circuit board arrived on the day of the first evaluation. There were 6 copies from both of the PCBs. They were soldered by 2 teammates on the workshop in the department. Solder-paste which had a mixture of solder and flux was used for soldering. The SMD components were placed by tweezers with the aid of the magnifying camera. A miniature hot plate was used to heat up the solder to proper temperature. The most challenging part was soldering PCAP04. Its QFN package made it difficult to have enough solder as well as prevent seeing if it was properly soldered. After soldering the SMD components, through hole components such as the JST headers and USB header were soldered using a soldering iron.

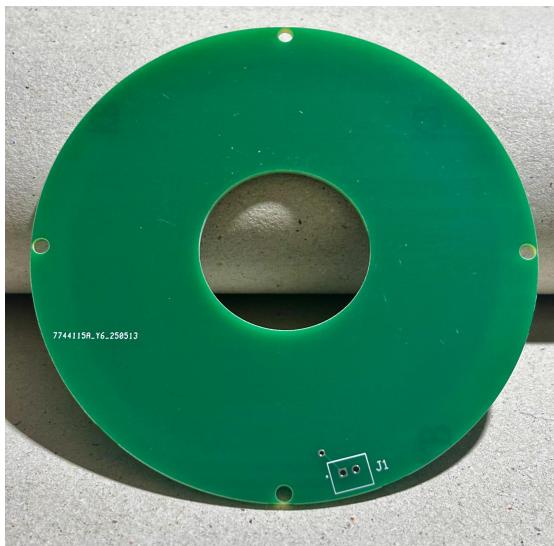
The PCB was tested in the analog laboratory. Firstly, continuity was checked using the continuity method in the digital multimeter. There seemed to be no shorted components. Since JTAG pins were added later, they could not be utilized in this device. The voltage levels of respective test points were measured to ensure the proper function of 3.3 V and 1.8 V regulators. Finally, SPI lines were observed with an oscilloscope to ensure that communication between MCU and PCAP04 was possible.



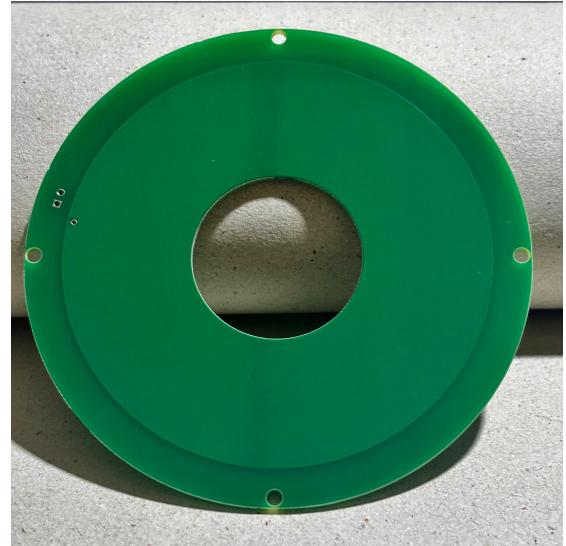
(a) Front Side of Primary PCB



(b) Back Side of Primary PCB



(c) Front Side of Secondary PCB



(d) Back Side of Secondary PCB

Figure 60: Front and Back Appearance of Both PCBs Before Soldering



Figure 61: Soldered Primary PCB

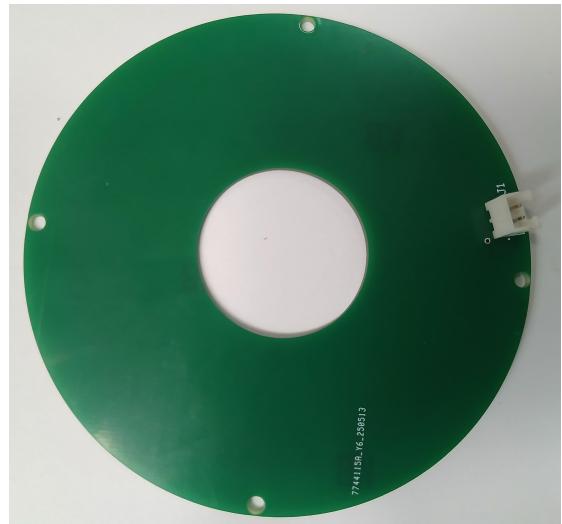


Figure 62: Soldered Secondary PCB

## 23.2 Final Mechanical Parts + Enclosure

The inner parts made for the first evaluation (metal disks, dielectric disk, and their holders) had slight errors in there dimensions. As a result, the metal disks and dielectric disks were touching, causing friction and therefore, inaccurate torque measurement. These parts were machined again with refined measurements to ensure proper operation of the device. These were then assembled using adhesives. The small size of disk holding poles prevent welding due to risk of melting. Also the closely packed nature makes it difficult.



Figure 63: Final Product

Not much changes were done to the Aluminum enclosure apart from adding a hole for USB port to come out of. This was done using a CNC drilling machine. Then the PCB spacers were attached to the 2 flat walls of the enclosure. These are used to hold the PCB with screws. Finally a coat of white paint was applied using the paint spray machine in the UAV lab.



Figure 64: The Internal Mechanical Parts Attached to the Shaft



Figure 65: Inside View

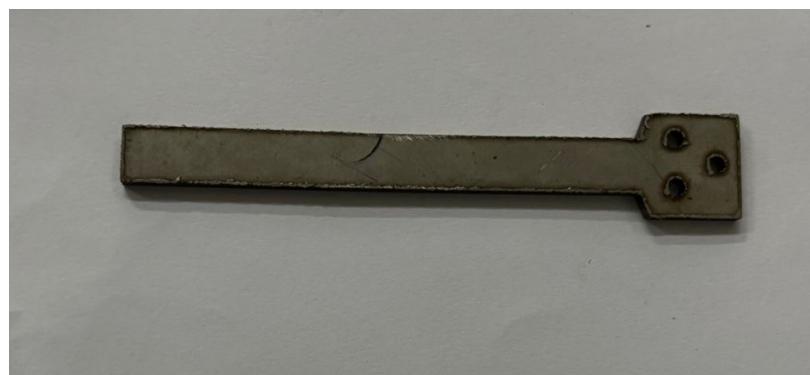


Figure 66: Handles to apply external Torque

### **23.3 Problems Encountered**

#### **At Initial Stage**

- Lack of reference material. While strain guage based torque sensors were common, capacitive torque sensors were not. Therefore, it took lot of effort to find a sensor to use as a reference design.
- Lack of information. Even after finding a capacitive torque sensor, its internal working were a mystery. The documentation provided by manufacturers did not describe internal workings. We had to research extensively till we found a patent describing design of a capacitive torque sensor.

#### **At Design Stage**

- Component Selection. Since the deformation is minuscule, we needed an extremely accurate way to measure torque. In addition to this, there was sampling rate requirement of 1000Hz. Finding a capacitance to digital converter to satisfy these needs was difficult.
- Finite Element Analysis. None of the group members had much mechanica/material engineering knowledge. So running simulations to choose shaft material and shape with best deformation was challenging. In addition to deformation requirement, there was also the requirement that device does not deform upto five times nominal torque. These constraints made designing shaft difficult.
- PCB Routing. Since the reference torque sensors were ssmall, we also had to reduce size as much as possible. This meant a small PCB. Also, since we use a copper pour on the ottom layer as the capacitor plate, routing was restricted to just 1 layer.

#### **At Final Stage**

- Soldering the PCB was difficult because PCAP04 was extremely small an was a QFN package. After soldering, there was no wy to know if it was propely connected.
- Since PCAP04 did not have much documentation available, the coding part was difficult. Also the available documentation contradicted each other at times.
- Due to the small size of PCAP04, it was difficult to debug it using multimeter and oscilloscope probe. Also since it was QFN package no pins were visible to test.
- The internal metal disks were a tight fit to the enclosure. Because of a slight tilt to the shaft, the metal disks tended to touch enclosure wall while rotating. Also JST wire makes the matter even worse because it must fit between metal disk and wall.

## 23.4 Project Timeline

21 February - Started reading a research paper from IEEE about a design of a novel capacitive torque sensor.

25 February - Watched videos about using torque sensors and identified user needs.

3 March - Read a patent about capacitor torque sensor design and identified a viable internal mechanism.

6 March - Evaluating conceptual designs.

15 March - Evaluated the capacitance measuring methods and decided on using a CDC.

28 March - 2 April - Did finite element analysis on shaft and decided on final shaft shape.

2 April - Evaluated dielectric materials and decided on FR4.

8 April - Evaluated MCUs and CDCs.

18 April - Decided on final MCU selection - ATmega32U4

20 April - Purchased aluminum for shaft and enclosure

23 April - Decided on final CDC selection - PCAP04

25 April - Finished coding the USB communication part on register level. Tested on development board

29 April - Designed the circuit and drew the schematics.

3 May - Ordered components

10 May - Did PCB design and routing

13 May - Ordered the PCB with 3 other teams.

18 May - Did machining and laser cutting for the enclosure and internal mechanical parts.

22 May - Had first evaluation

1 July - Soldered the PCB in department workshop.

2 July - Started coding the PCAP04 interfacing with the MCU.

7 July - Did laser cutting and machined the hole in enclosure for USB.

10 July - Did final assembly and painted the enclosure.

## 23.5 Complete Project Budget

### Electronic Components - Mouser

| Component                               | Mouser Product Code    | Quantity | Price (Rs.)      |
|---|------------------------|----------|------------------|
| ESD Protection Diodes                   | 652-CG0603MLC-05E      | 10       | 454.95           |
| Resettable Fuses                        | 576-1812L050PR         | 10       | 973.6            |
| 1.8V Voltage Regulator                  | LP5907MFX-1.8/NOPB     | 5        | 743              |
| 3.3V Voltage Regulator                  | TPS73633DBVR           | 4        | 2608.4           |
| 16MHz Clock Oscillator                  | ECS-8FMX-160-TR        | 3        | 3776.085         |
| Wire Headers                            | 82BXHAM(LF)(SN)        | 7        | 360.9            |
| 1uF Capacitor                           | KAM21BR71H104JT        | 20       | 770.38           |
| 0.1uF Capacitor                         | KGM21AR71C105JU        | 10       | 500.5            |
| 10uF Capacitor                          | C0805C106J8RACAUTO7210 | 10       | 1686.34          |
| 0.01uF Capacitor                        | 0805ZC103JAT2A         | 10       | 506.5            |
| 4.7uF Capacitor                         | C0805X475J8RAC7800     | 10       | 1668.15          |
| 22 Resistor                             | ERJ-T06J220V           | 10       | 315.4            |
| 330 Resistor                            | 560112120014           | 10       | 424.6            |
| 10k Resistor                            | RK73B2ATTE103J         | 10       | 81.9             |
| Ferrite Bead                            | MMZ1005F181ETD25       | 10       | 461.2            |
| PCAP04 Capacitance to Digital Converter | PCAP04-AQFM-24-V2      | 4        | 9293.11          |
| ATmega32U4 Microcontroller              | ATMEGA32U4-AU          | 4        | 6417.82          |
| <b>Total</b>                            |                        |          | <b>31042.835</b> |

Shipping = Rs. 14200.85

Taxes = Rs. 9000

**Total = Rs. 54243.685**

### Components - Local

| Component            | Quantity | Price (Rs.) |
|----------------------|----------|-------------|
| USB Cable            | 1        | 250         |
| USB Ports            | 5        | 75          |
| Development Board    | 1        | 1760        |
| JST Cable + Header   | 5        | 550         |
| PCB Holders + Screws | 10       | 530         |
| Solder Paste         | 1        | 1000        |
| <b>Total</b>         |          | <b>3165</b> |

### Components - Ali Express

| Component                 | Quantity | Price (Rs.)    |
|---------------------------|----------|----------------|
| 6803 Bearings             | 10       | 340.87         |
| 1mm Thick FR4 30cm x 30cm | 1        | 3150.20        |
| <b>Total</b>              |          | <b>3491.07</b> |

Shipping + Taxes = Rs. 3950

**Total = Rs. 7441.07**

#### PCB Expenses

PCB Price + Shipping = Rs. 12350

Tax = Rs. 2612

**Total = Rs. 14962**

#### Enclosure and Inner Parts

| Description                  | Price (Rs.)  |
|------------------------------|--------------|
| Aluminum Cylinder + Rod      | 4800         |
| Laser Cutting                | 7710         |
| Metal Sheets (5mm + 3mm)     | 2300         |
| Metal Sheet (1mm)            | 650          |
| Metal Sheet (6mm)            | 300          |
| Metal Work (Lathe Machining) | 3500         |
| Welding                      | 1200         |
| Alan Bolt                    | 450          |
| Sandpaper + Glue             | 1240         |
| Paint                        | 715          |
| <b>Total</b>                 | <b>22865</b> |

$$\begin{aligned}\text{Total Expenses (Rs.)} &= 22865 + 7441.07 + 14962 + 3165 + 54243.685 \\ &= 102,676.755\end{aligned}$$